# **Compal Confidential**

VALGC\_GD M/B Schematics Document

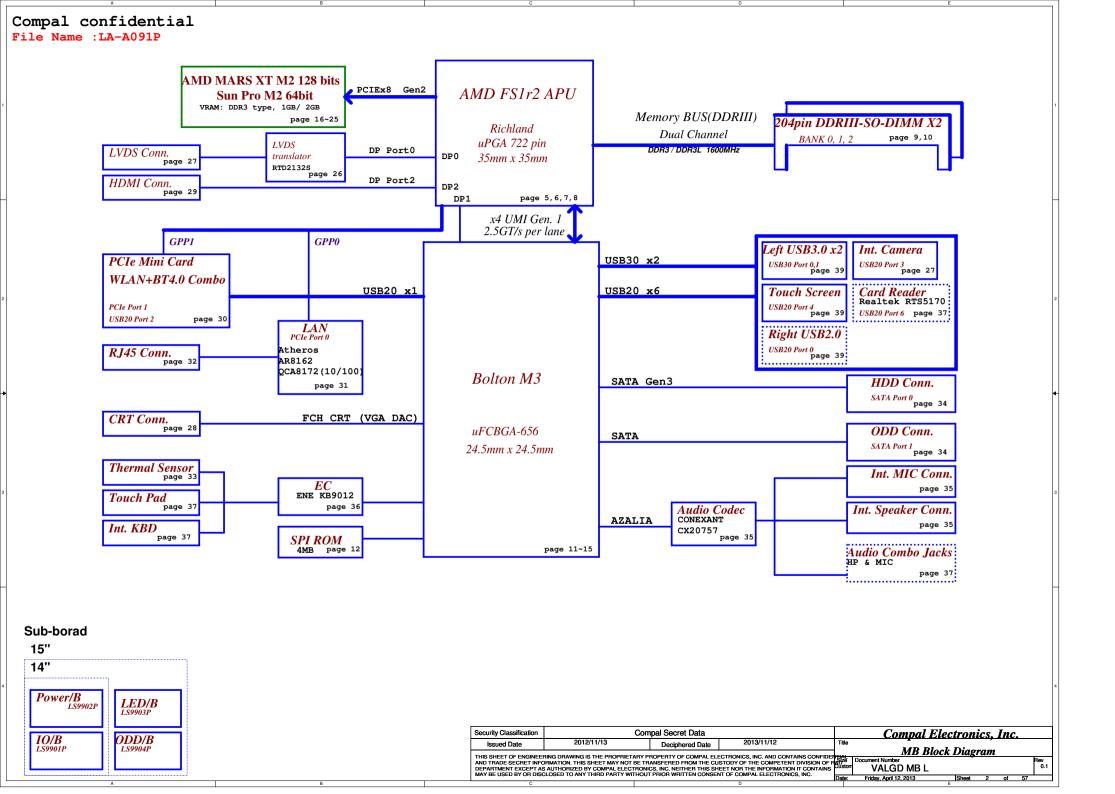
AMD Fs1r2 Richland Processor with DDRIII + Bolton-M3 FCH
AMD Mars XT M2

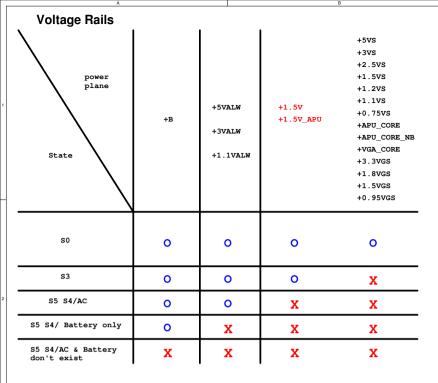
LA-A091P

2013-04-16

REV:1.0

Security Classification	Con	npal Secret Data		Com	pal Electronic	s, Inc.	
Issued Date	2012/11/13	2012/11/13 Deciphered Date 2013/11/12			Cover Page		
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	NODROM	>७<	ıı⊲⊢⊢	大田 のの 中 の	WOD ₹5	≱ kZ ≥≥ 4Z	Nac no r	LUI	<b>⋖1</b> ⊃	R FO NHWN
ME U JUVĀ 4H	¥M WOHN	×	≥ ≥	×	×	×	×	×	×	×
N CN_N SQ∩R B SB	V W W O – N	×	×	×	×	×	×	×	<b>&gt;</b>	×
MOT NO 4140 MOT NO TRO	ЩUI **>VI	×	×	×	<b>→</b> v	<b>&gt;</b> v	×	×	×	×
ME WIND DAN	ΜΟ Ν <b>Ι Μ</b> ΉΩΓ↓ - WΟΝ ⊼ΠΙΟΟΗΝ	>	×	×	×	×	>	×	×	>

## EC SM Bus1 address EC SM Bus2 address

Device	Address	Device	Address
Smart Battery	0001 011X b	Thermal Sensor	1001_101xb
		SB-TSI(default)	1001_100xb
		VGA(int. thermal)	1000_001xb
		RTD2132S	1010_1000b
		VGA(oxt thormal)	0100 1101b

#### **PCH SM Bus address**

Device	Address
DDR DIMM0	1001 000Xb
DDR DIMM2	1001 010Xb

SIGNAL	SLP_S3#	SLP_S5#	+VALW	+V	+VS	Clock
Full ON	HIGH	HIGH	ON	ON	ON	ON
S1 (Power On Suspend)	HIGH	HIGH	ON	ON	ON	LOW
S3 (Suspend to RAM)	HIGH	HIGH	ON	ON	OFF	OFF
S4 (Suspend to Disk)	LOW	HIGH	ON	OFF	OFF	OFF
S5 (Soft OFF)	LOW	LOW	ON	OFF	OFF	OFF

#### **BOARD ID Table**

#### Board ID / SKU ID Table for AD channel

Board ID	PCB Revision
0	
1	
2	0.2
3	
4	
5	
6	
7	

ID	BRD ID	Ra	Rb	Vab
0	R10 MP	x	0	0V
1	R03 PVT	100K	8.2K	0.25V
2	R02 DVT	100K	18K	0.5V
3	R01 EVT	100K	33K	0.82V

**BOM Structure Table** 

#### **USB Port Table**

USB 2.0	USB	3.0	Port	4 External USB Port			
			0	USB Port 2.0 (Right Side)			
			1				
			2	Mini Card(WLAN)			
			3	Camera /			
			4	Touch Screen			
			5				
			6	Card Reader			
						7	
			8				
			9				
	XHCI	0	10	USB 2.0 Port (Left Side)			
		1	11	USB 2.0 Port (Left Side)			
		2	12				
			13				

**USB OC MAPPING** 

oc#	USB	Port
0	USB20 port10,port11	USB30 port0,port1
1	USB20 port0	
2		
3		

APU PCIE PORT LIST

ALU E	AFU FUIL FUIT LIST				
Port	Device				
1	LAN				
2	WLAN				
3					
4					
	•				

**FCH PCIE PORT LIST** 

1	Port	Device
1	1	
1	2	
1	3	
]	4	

BOM Structure	BTO Item
PX@	VGA circuit
140	For 14"
15@	For 15"
45@	HDMI LOGO
CMOS@	CMOS Camera part
8162@	AR8162 LAN part
8172@	AR8172 LAN part
CMOS@	For CMOS circuit
TS@	For Touch Screen circuit
X76@	X76 Level part for VRAM
GCLK@	Ues GCLK circuit
NOGCLK@	No use GCLK circuit
GCLK302@	302 part for DIS
GCLK238@	238 part for UMA
LVDS@	LVDS circuit
PXNOGCLK@	No use GCLK circuit in GPU
LDO@	LDO mode for LAN
SWR@	SWR mode for LAN
DEBUG@	For debug
ME@	ME part
MIC@	MIC part
885N@	Unpop in KBC page
JUMP@	JUMP
TEST POINT@	TSET POINT
SHORT PAD@	SHORT PAD
EMI@	EMI part
@ESD@	Reserve for ESD
@EMI@	Reserve for EMI
@	Unpop
MARS@	VRAM CHB parts for MARS
2132S@	Panel PWM part for RTD2132S
2132R@	Panel PWM part for RTD2132R
ShareROM@	Reserve for ShareROM
Strap@	Reserve for Strap pin

Ra = R310Rb = R311

	X76@ Mars XT	X76@ Mars XT VRAM STRAP			X76@		
	Vendor UV5,UV6,UV7,UV8, UV9,UV10,UV11,UV12	PS_3[3]	PS_3[2]	PS_3[1]	R_pu RV20	R_pd RV27	
MS2G	Samsung 2048Mbits SA000068U00 128M16 K4W2G1646E-BC1A FBGA	0	0	0	NC	4.75K	
MM2G	Micron 2048Mbits SA000067500 128Mx16 MT41J128M16JT-093G:k	0	0	1	8.45K	2K	
MH2G	Hynix 2048Mbits SA000065300 128M16 H5TQ2G63DFR-NOC FBGA	0	1	0	4.53K	2K	

		X76@					
		Vendor UV9,UV10,UV11,UV12	PS_3[3]	PS_3[2]	PS_3[1]	R_pu RV20	R_pd RV27
SS2G		Samsung 2048Mbits SA000068R00 256M16 K4W4G1646B-HC11 FBGA	0	0	0	NC	4.75K
SM2G		Micron 2048Mbits SA000065D00 256M16 MT41K256M16HA-107G	0	0	1	8.45K	2K
SS1G		Samsung 1024Mbits SA000068U00 128M16 K4W2G1646E-BC1A FBGA	0	1	1	6.98K	4.99K
SM1G		Micron 1024Mbits SA000067500 128Mx16 MT41J128M16JT-093G:k	1	1	0	3.4K	10K
SH1G		Hynix 1024Mbits SA000065300 128M16 H5TQ2G63DFR-N0C FBGA	1	1	1	4.75K	NC

### Power-Up/Down Sequence

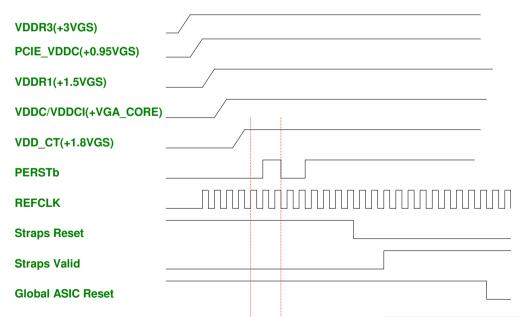
"Mars" has the following requirements with regards to power-supply sequencing to avoid damaging the ASIC:

All the ASIC supplies must reach their respective nominal voltages within 20ms of the start of the ramp-up sequence, though a shorter ramp-up duration is preferred. The maximum slew rate on all rails is 50mV/us.

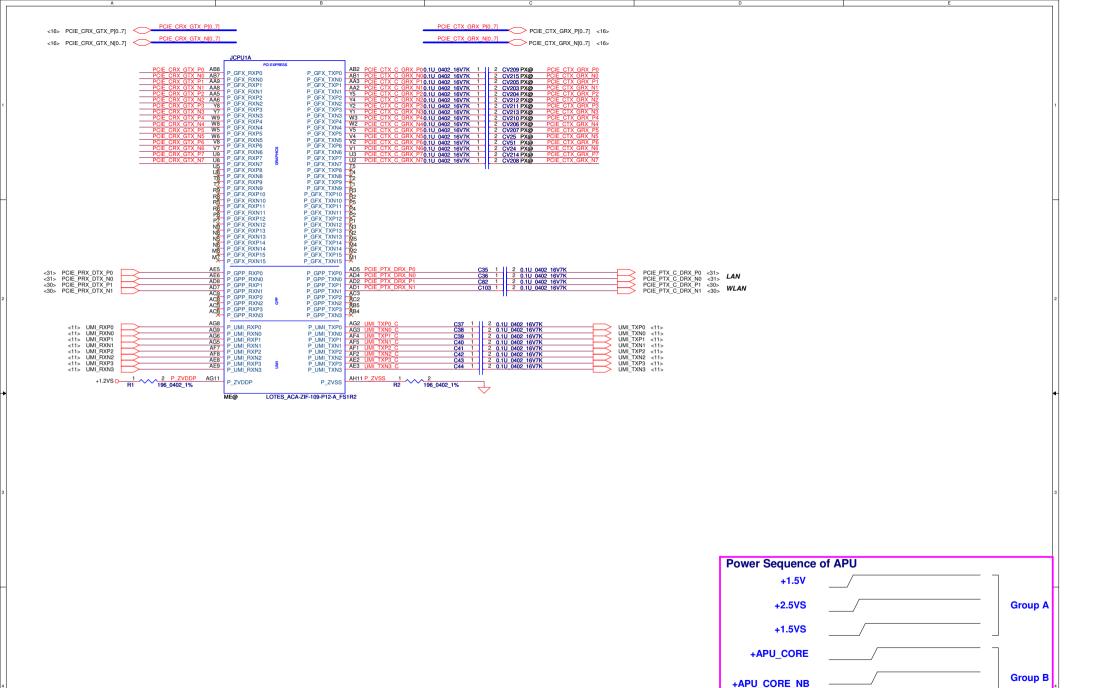
The external pull ups on the DDC/AUX signals (if applicable) should ramp up before or after both VDDC and VDD\_CT have ramped up.

VDDC and VDD\_CT should not ramp up simultaneously. For example, VDDC should reach 90% before VDD\_CT starts to ramp up (or vice versa).

For power down, reversing the ramp-up sequence is recommended.

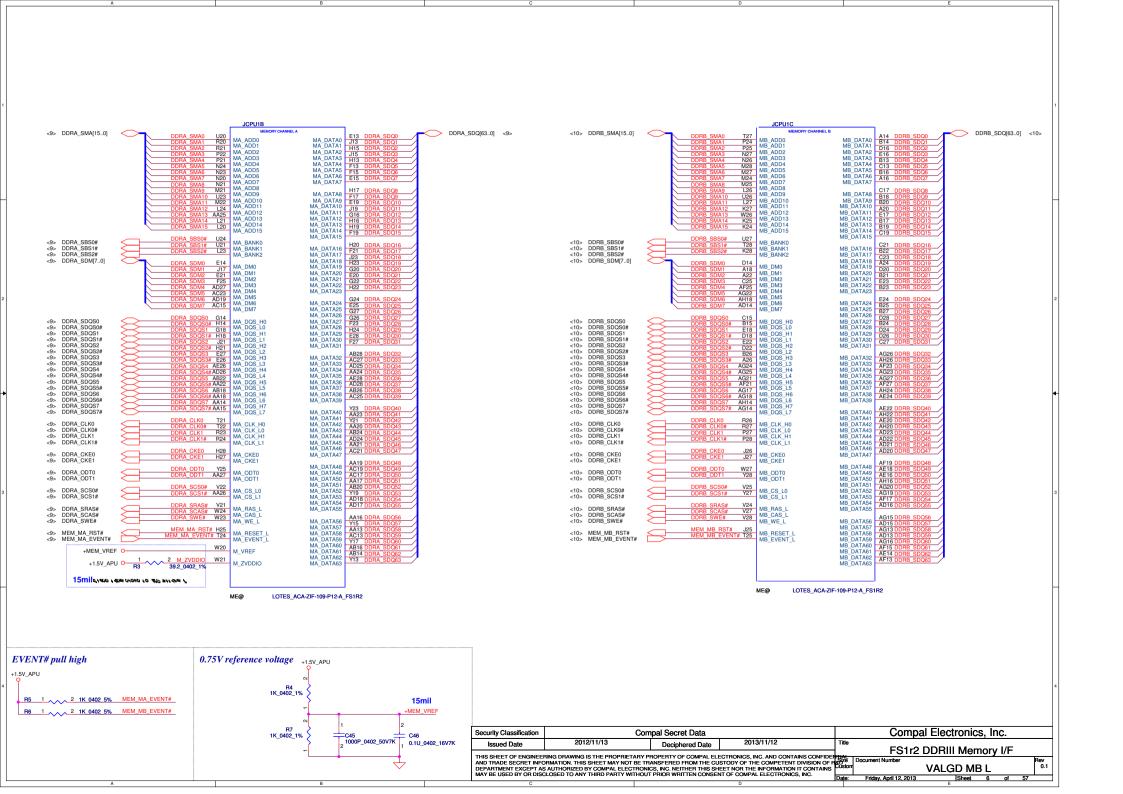


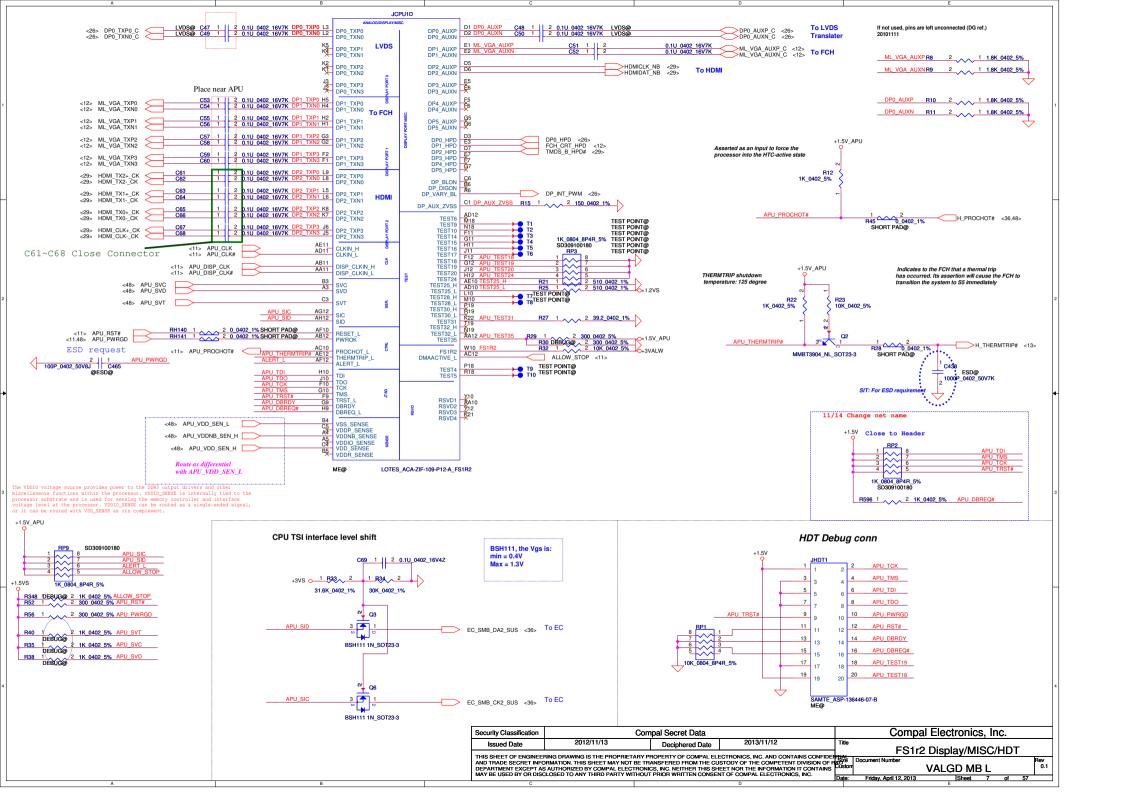
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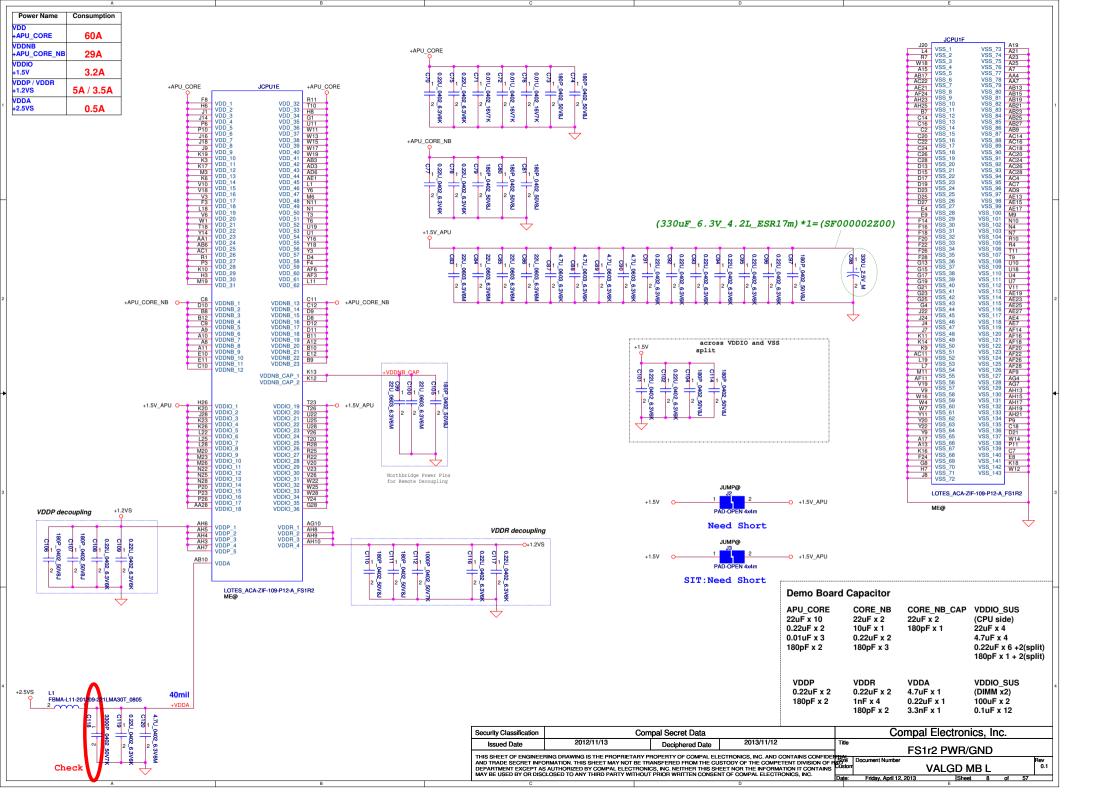


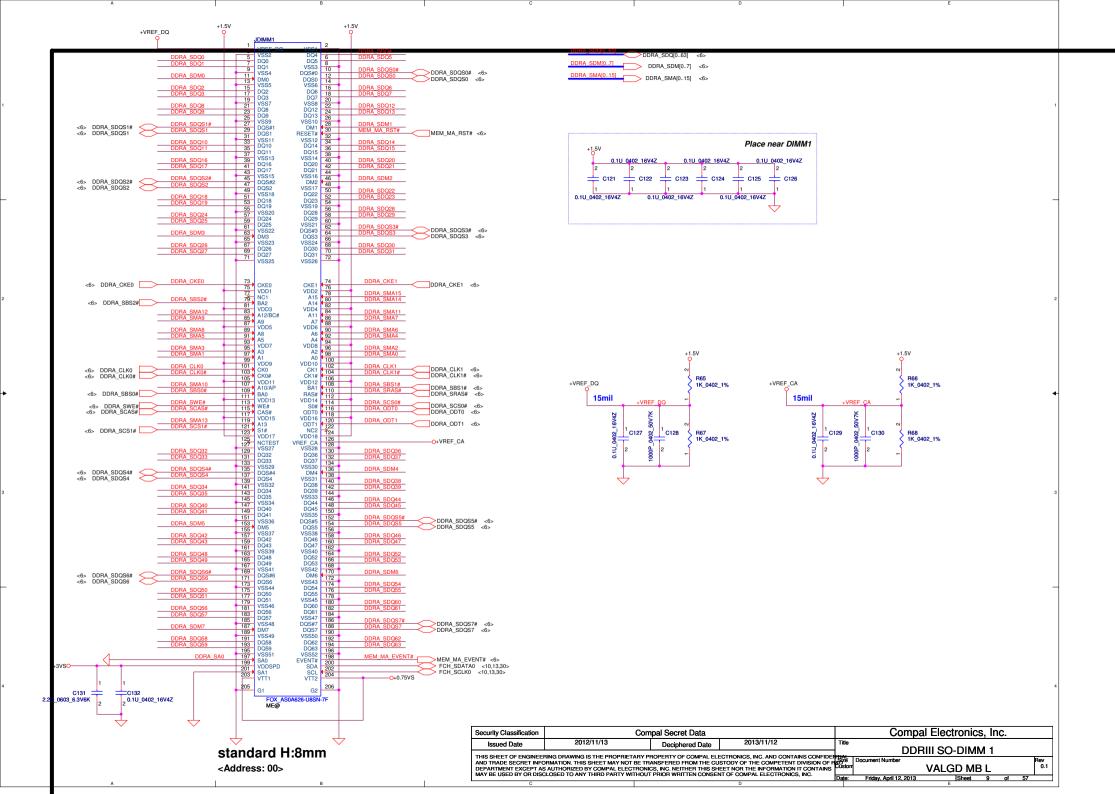
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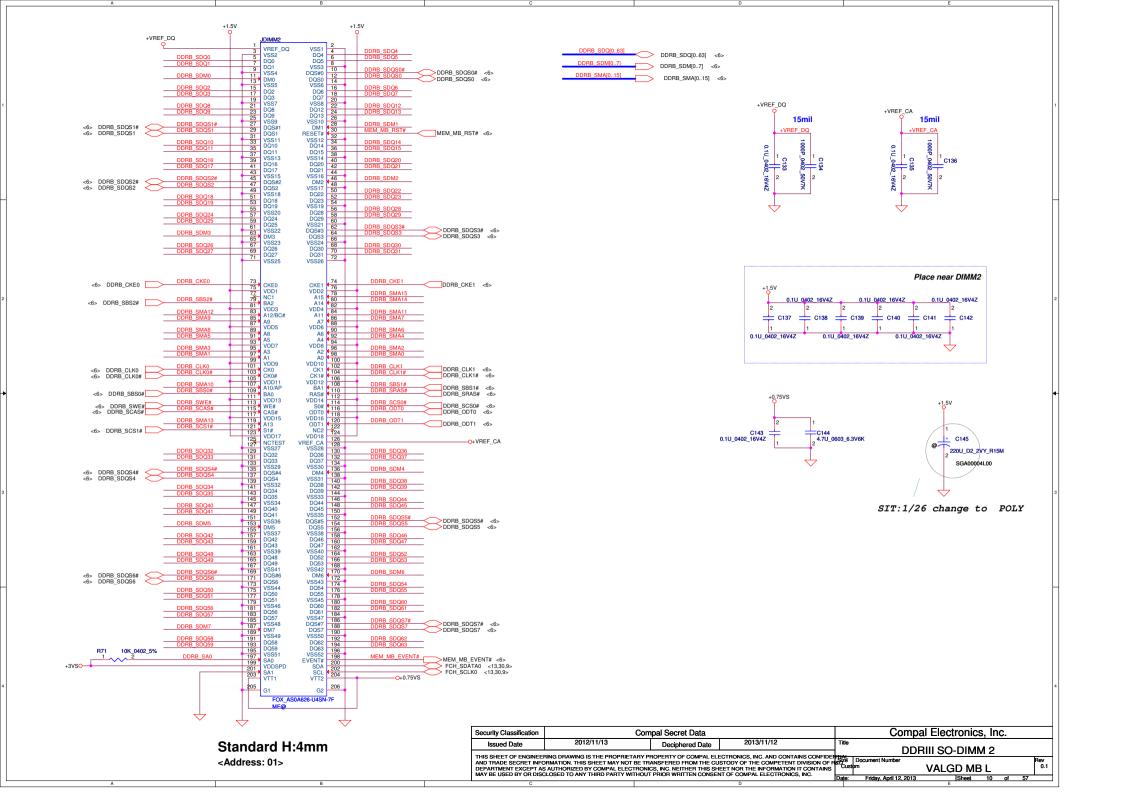
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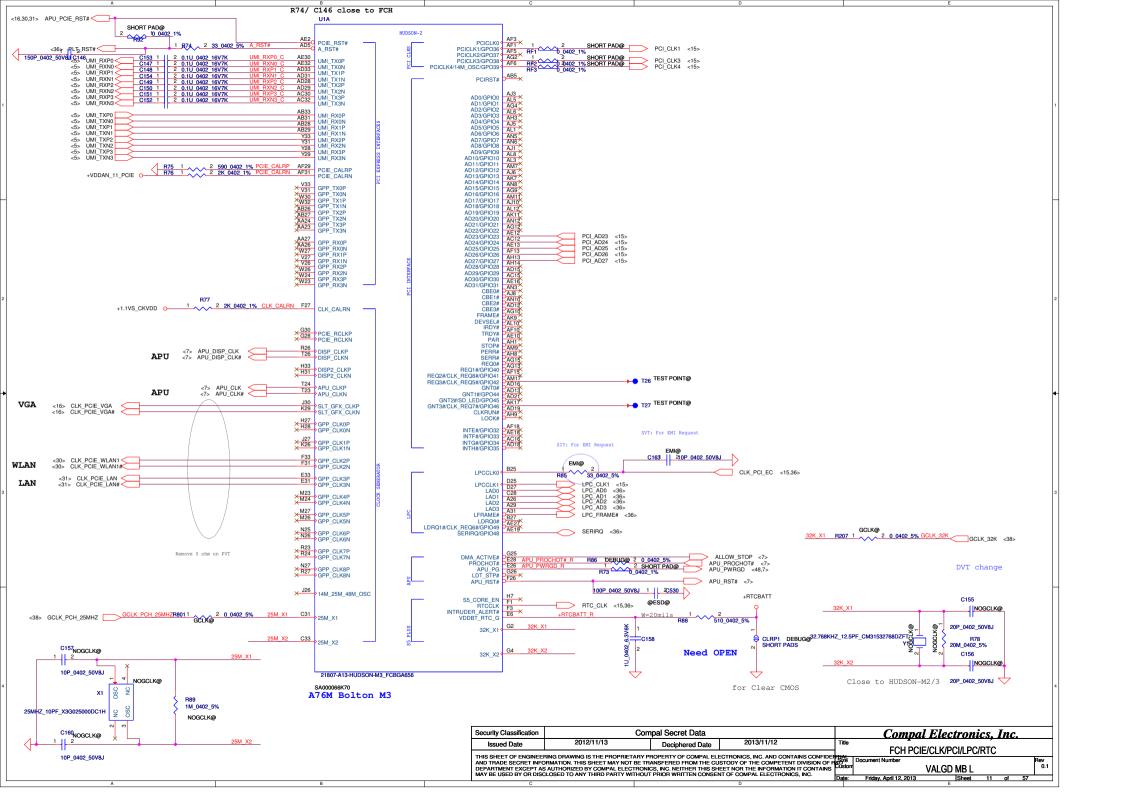


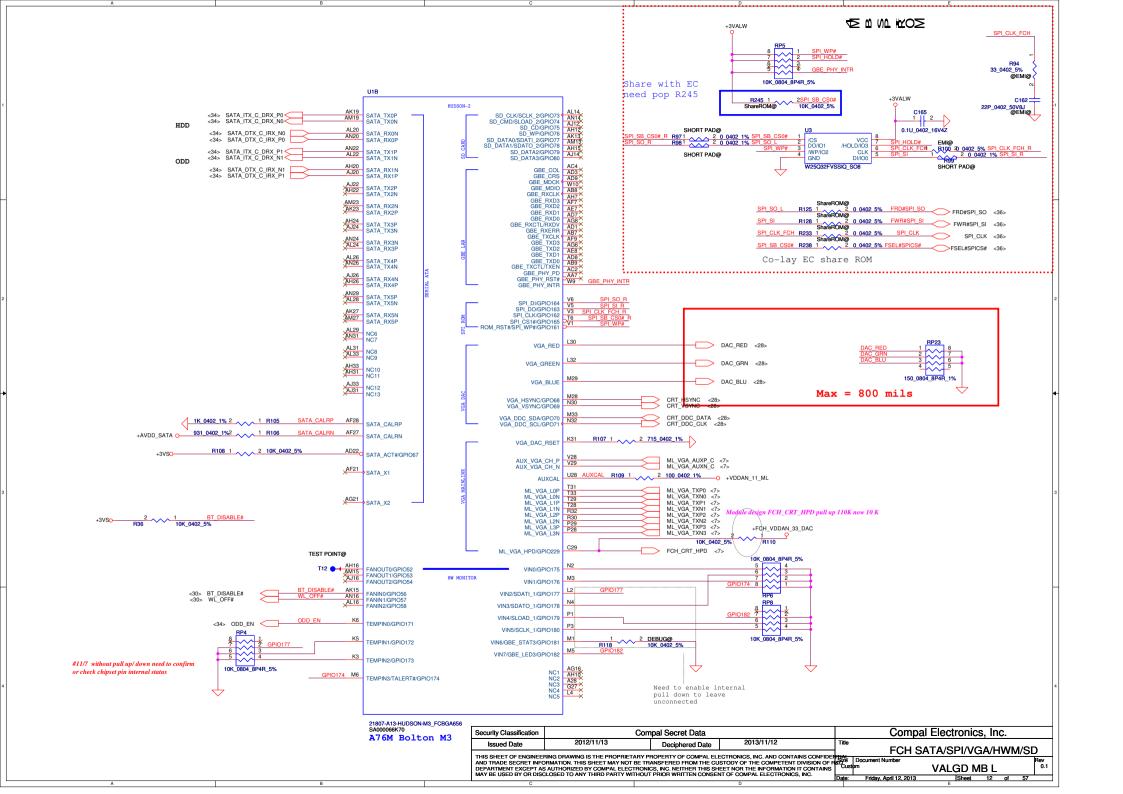


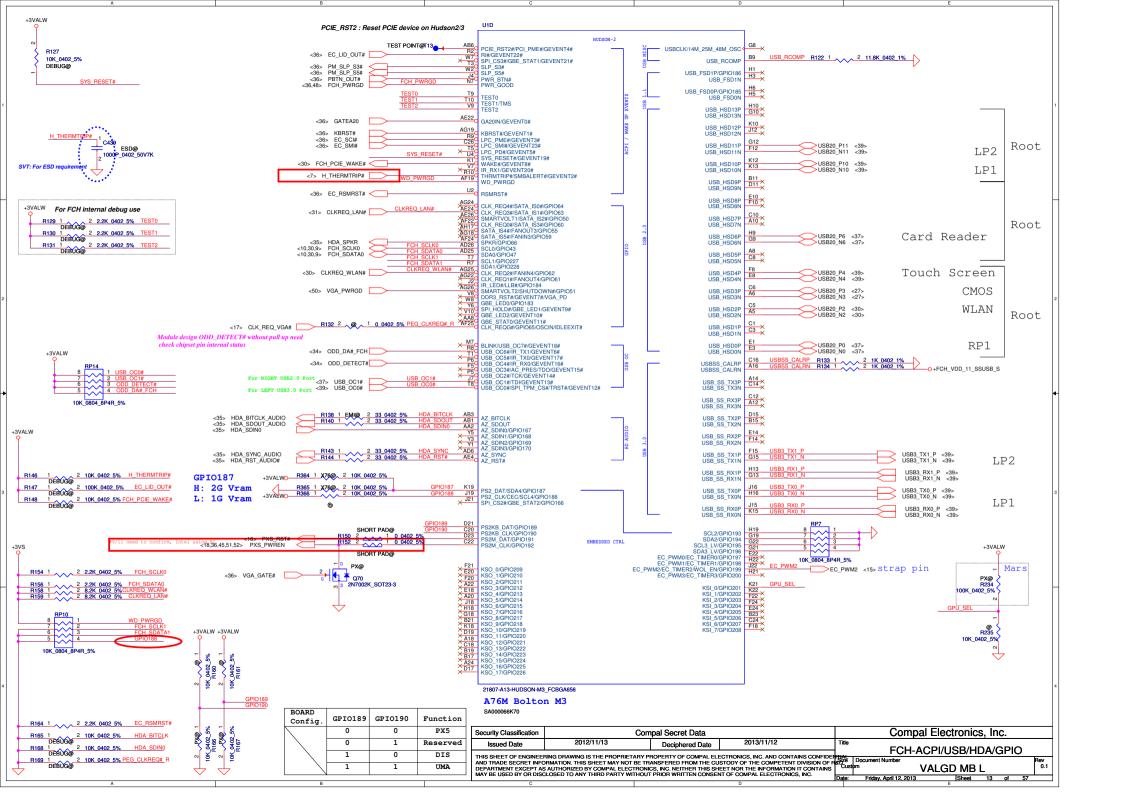


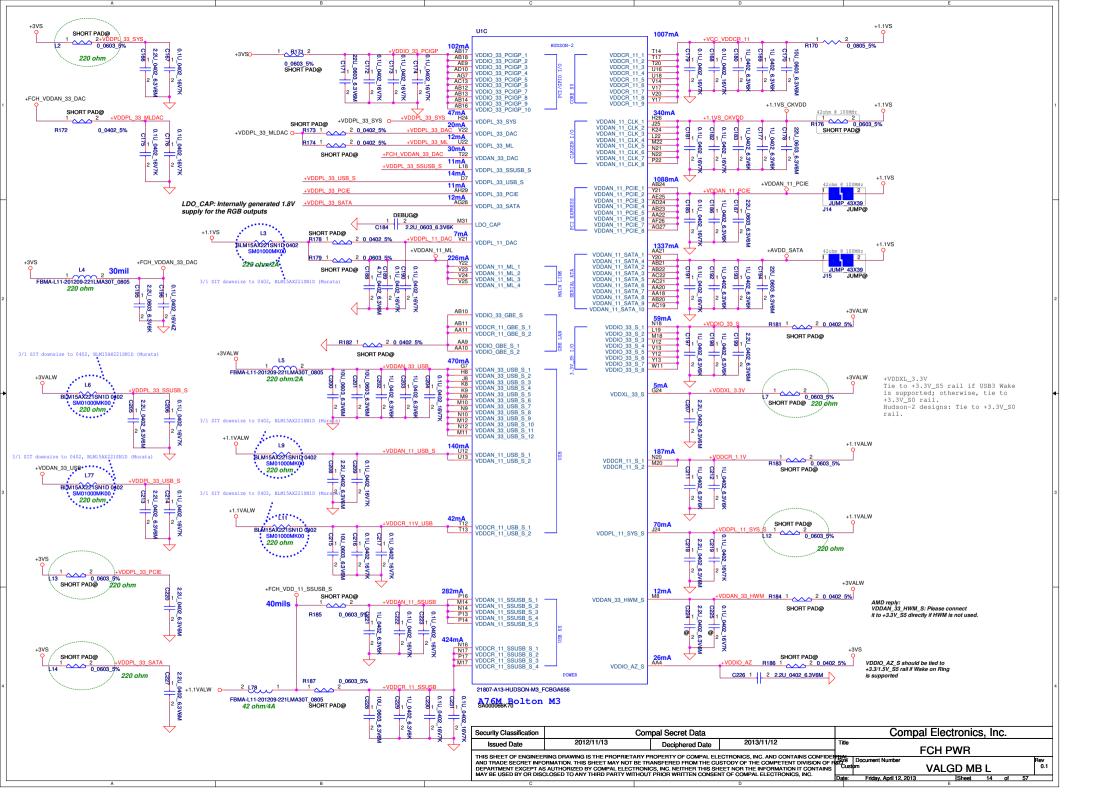


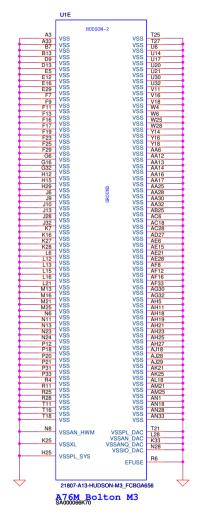












#### **STRAP PINS**

PULL HIGH

**PULL** 

LOW

PCI CLK1

ALLOW PCIE GEN2

FORCE PCIE GEN1

DEFAULT

PCI CLK3

USE DEBUG

STRAPS

PCI CLK4

NON\_FUSION CLOCK MODE

CLK PCI EC

EC ENABLED

EC DISABLED

LPC CLK1

CLKGEN ENABLED

DEFAULT

CLKGEN DISABLE

EC PWM2

SPI ROM

RTC CLK

S5 PLUS MODE

DISABLED

DEFAULT

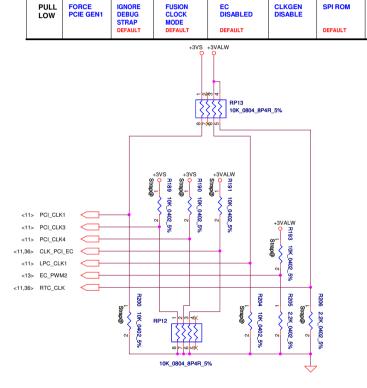
S5 PLUS

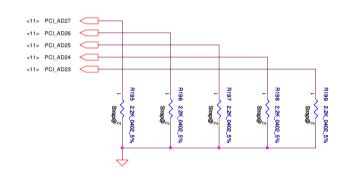
MODE ENABLED

#### **DEBUG STRAPS**

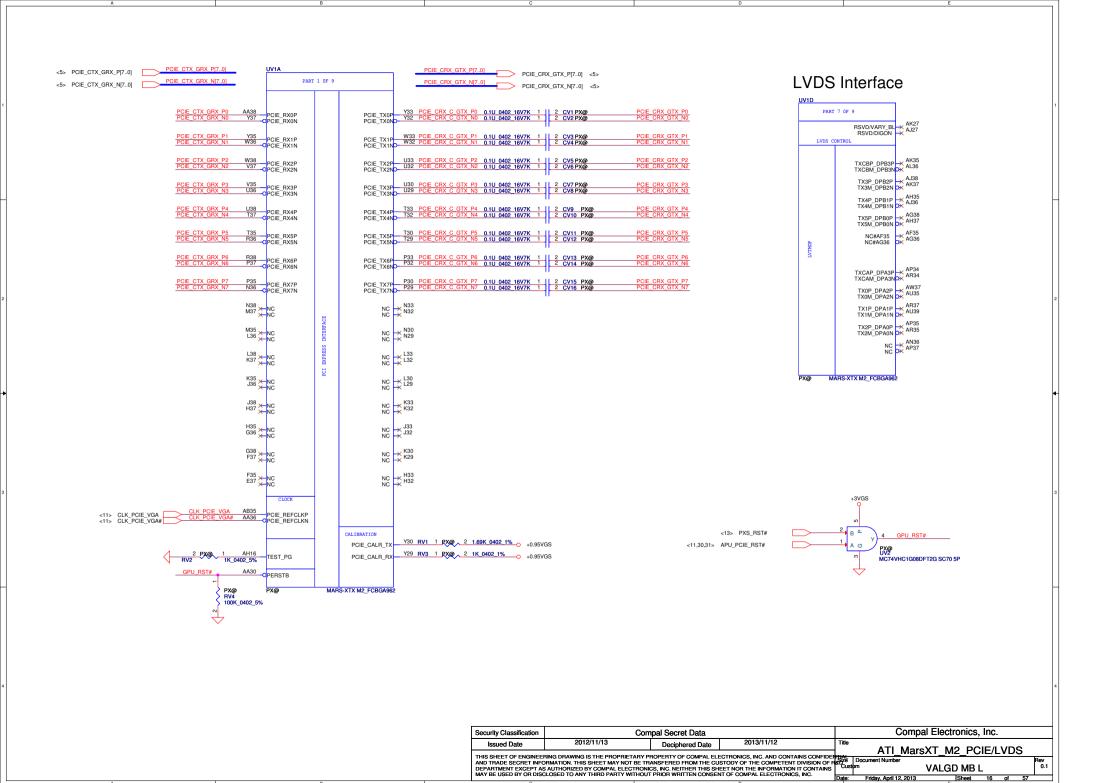
#### FCH HAS 15K INTERNAL PU FOR PCI AD[27:23]

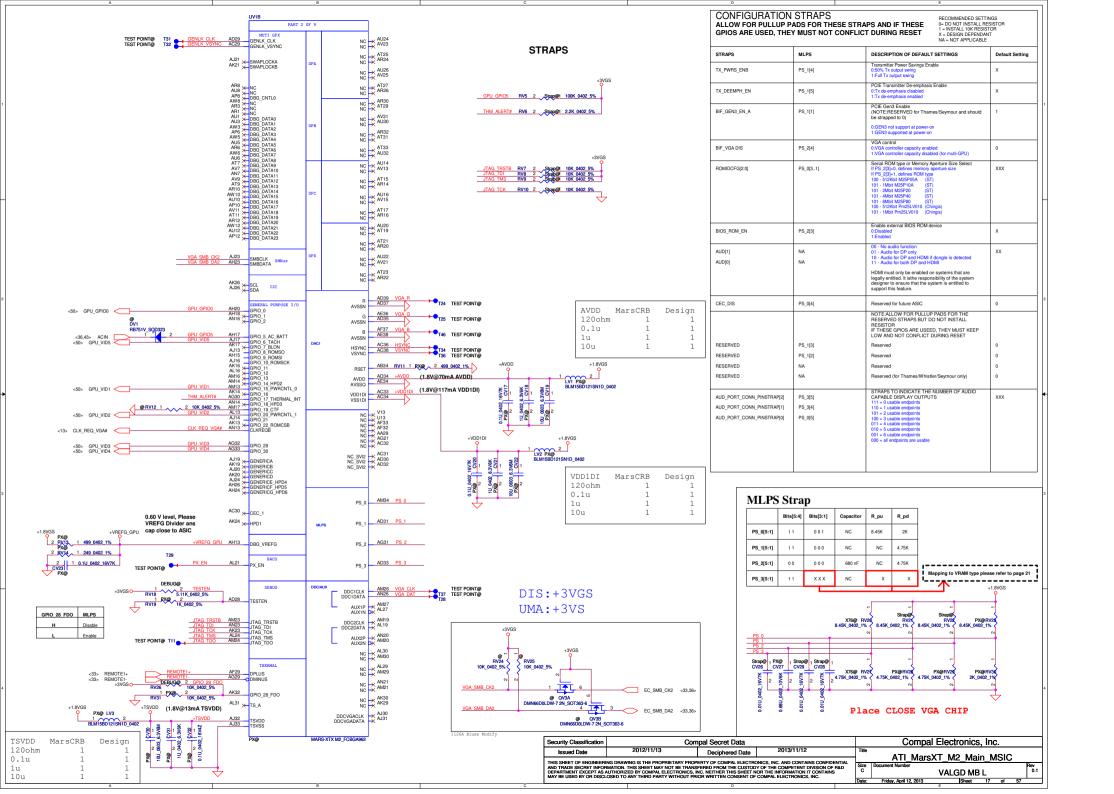
	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL	DISABLE ILA AUTORUN	USE FC PLL	USE DEFAULT PCIE STRAPS	DISABLE PCI MEM BOOT
	DEFAULT	DEFAULT	DEFAULT	DEFAULT	DEFAULT
PULL LOW	BYPASS PCI PLL	ENABLE ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	ENABLE PCI MEM BOOT

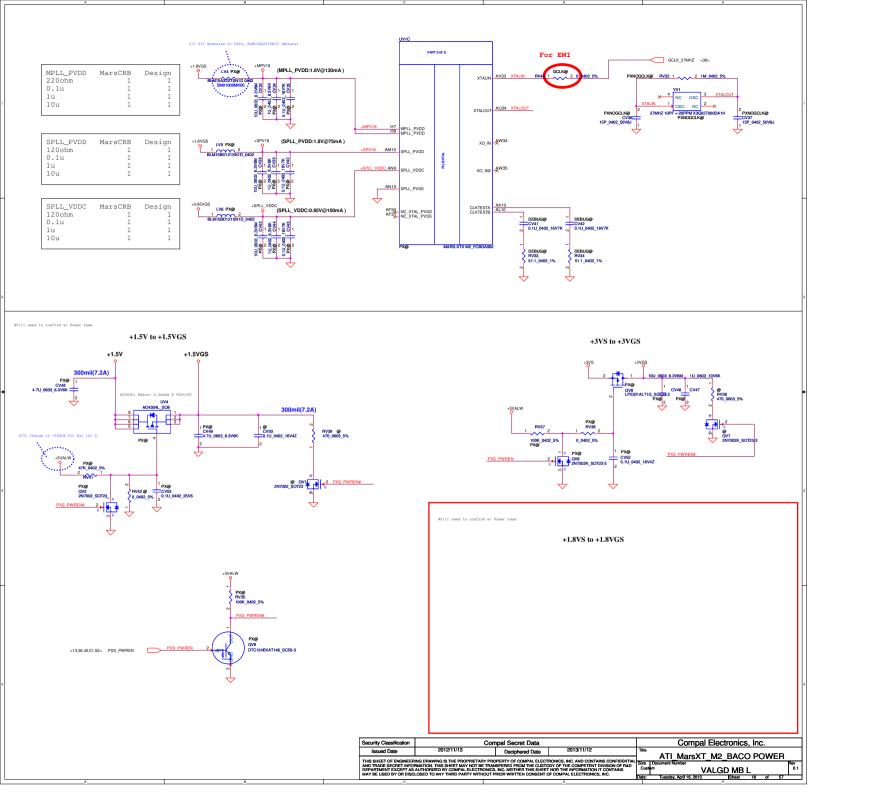


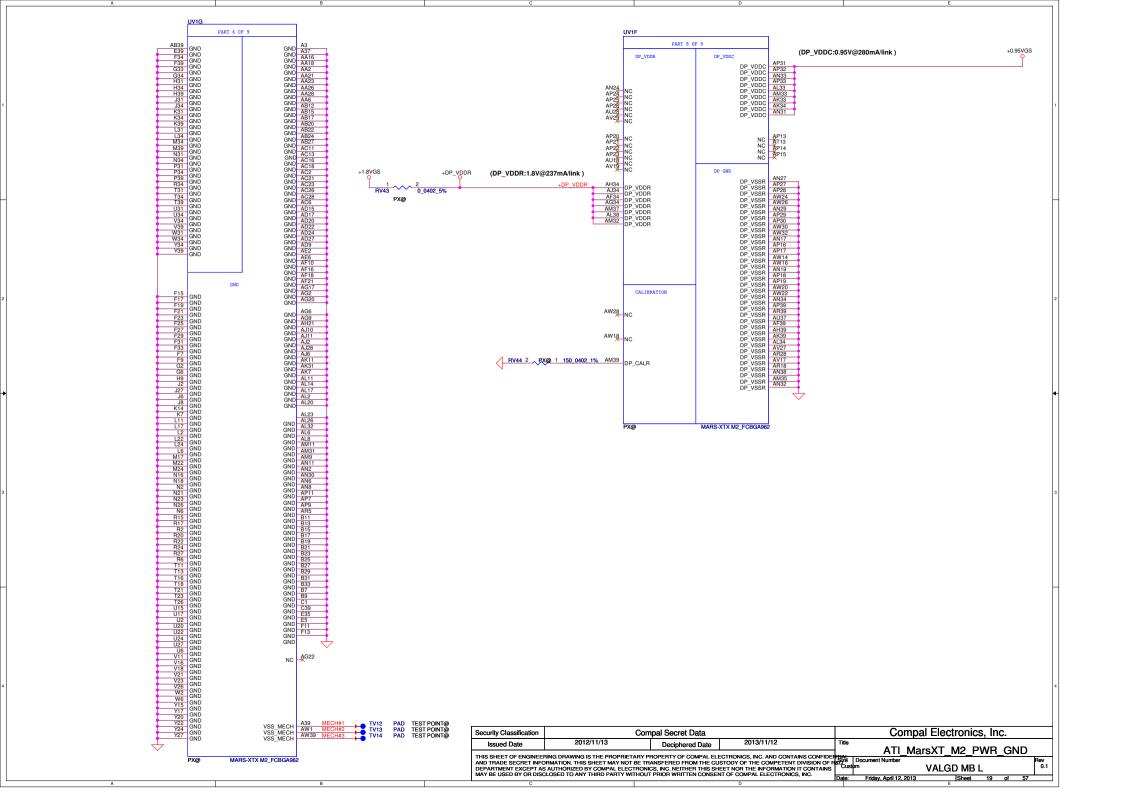


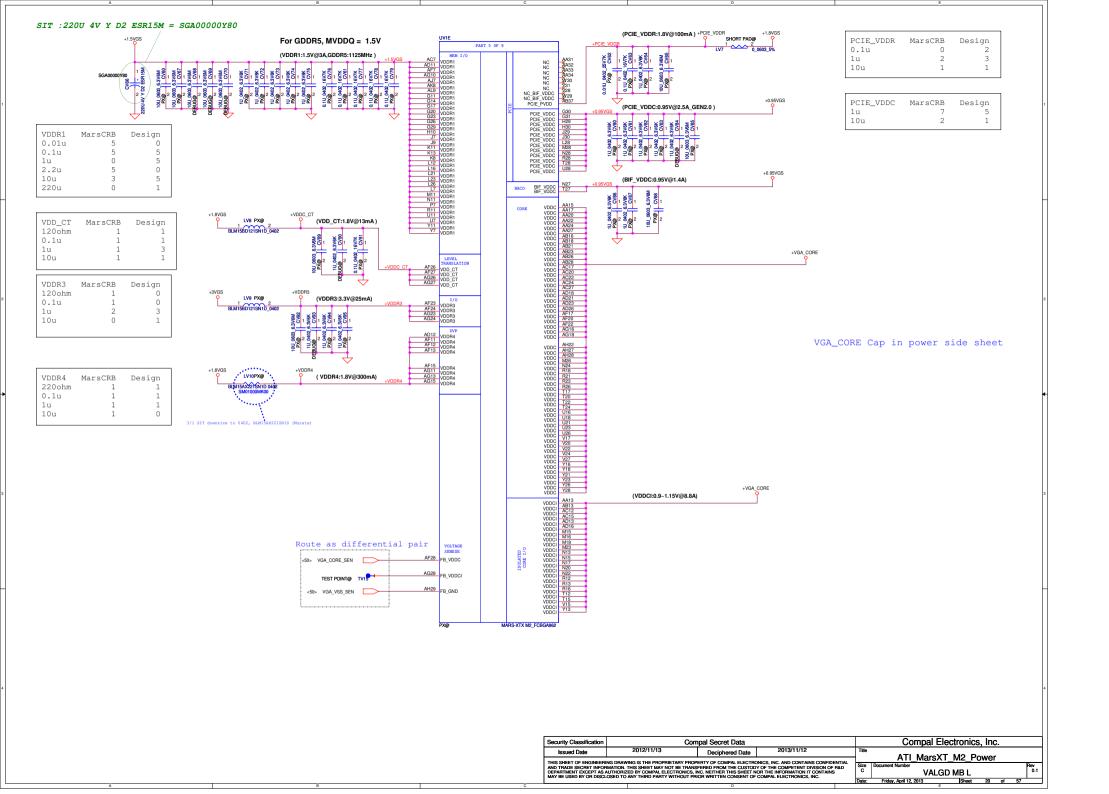
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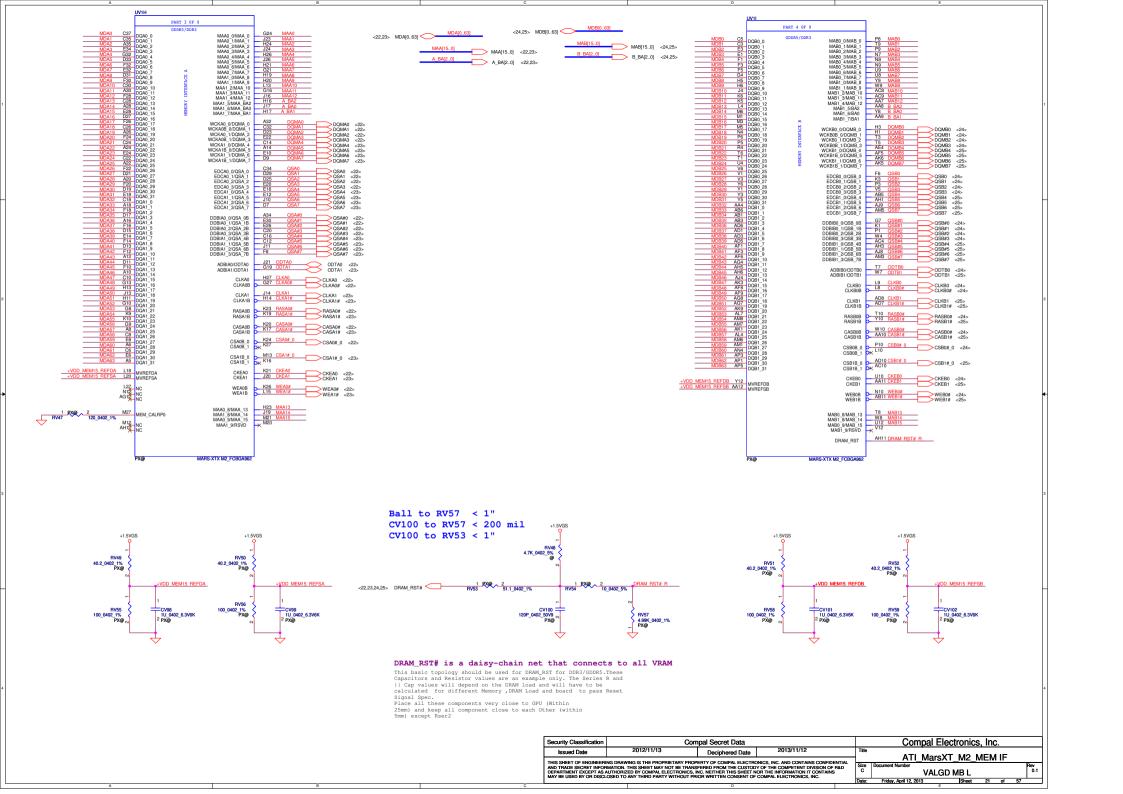


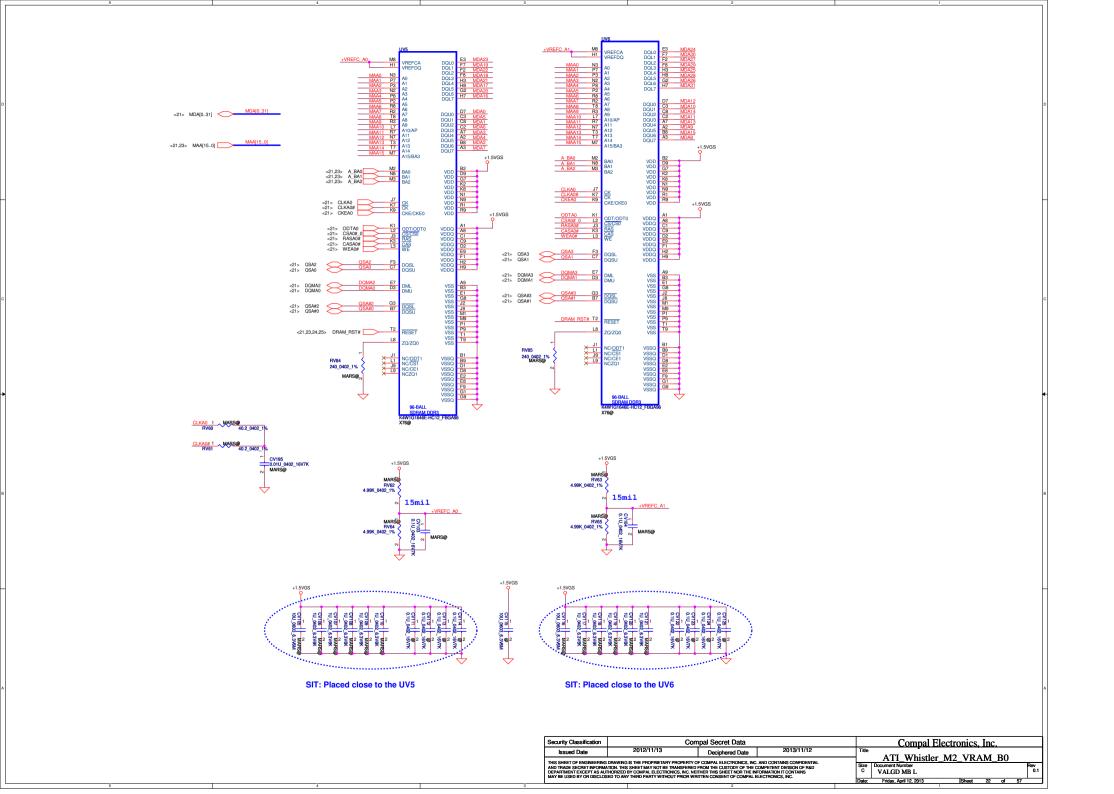


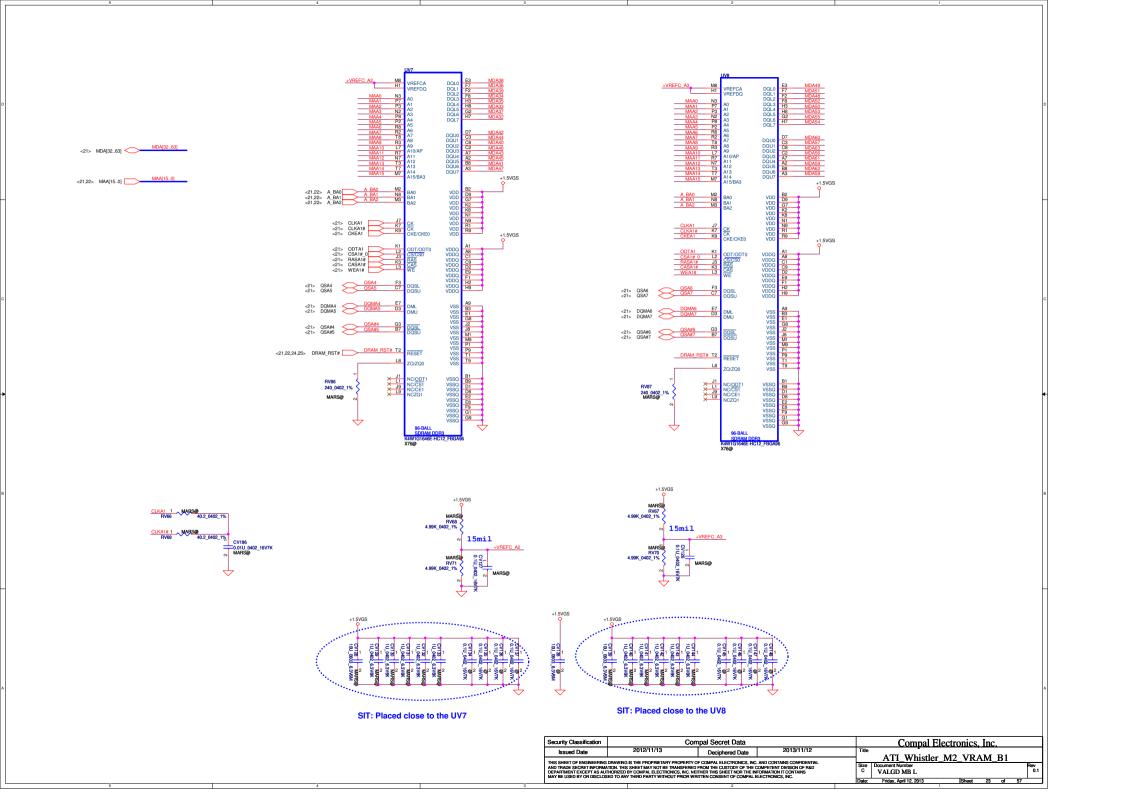


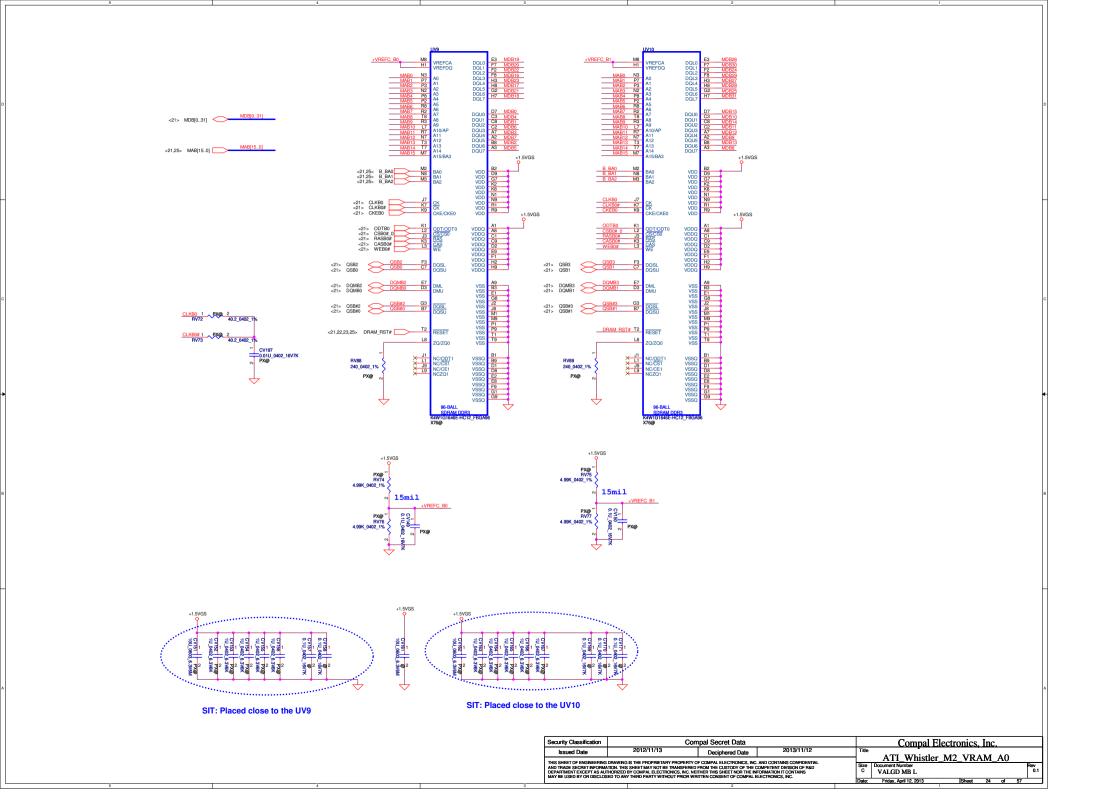


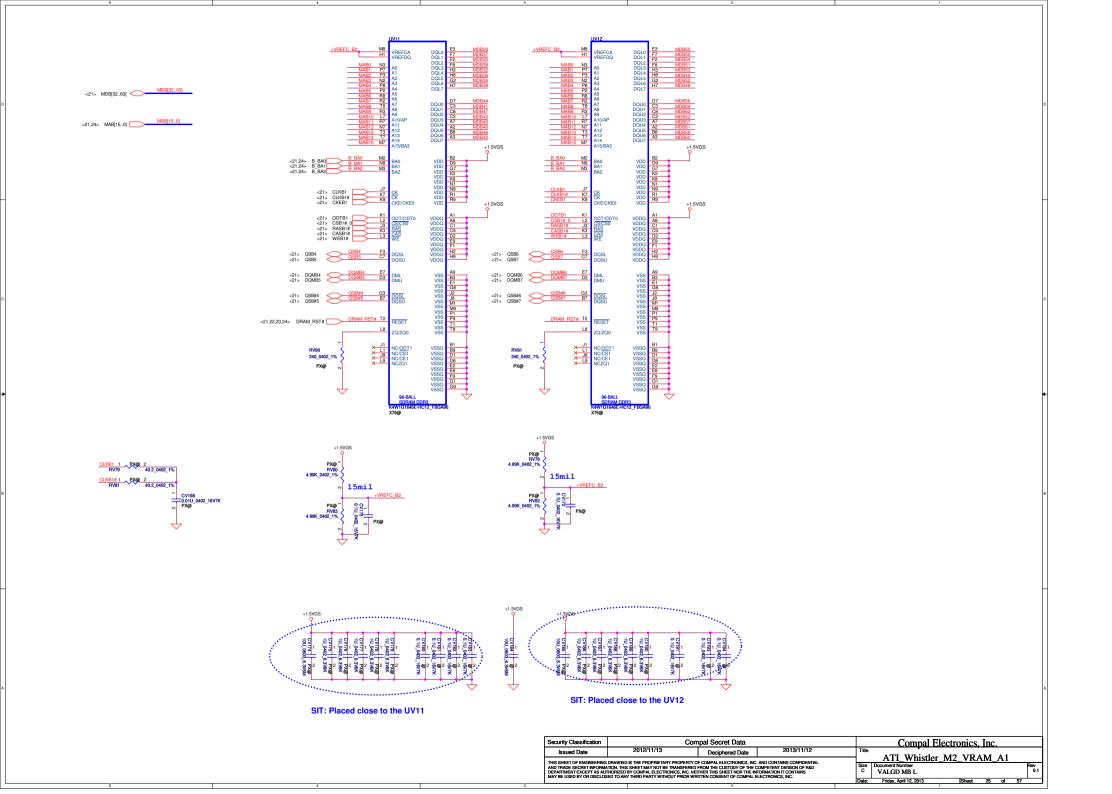


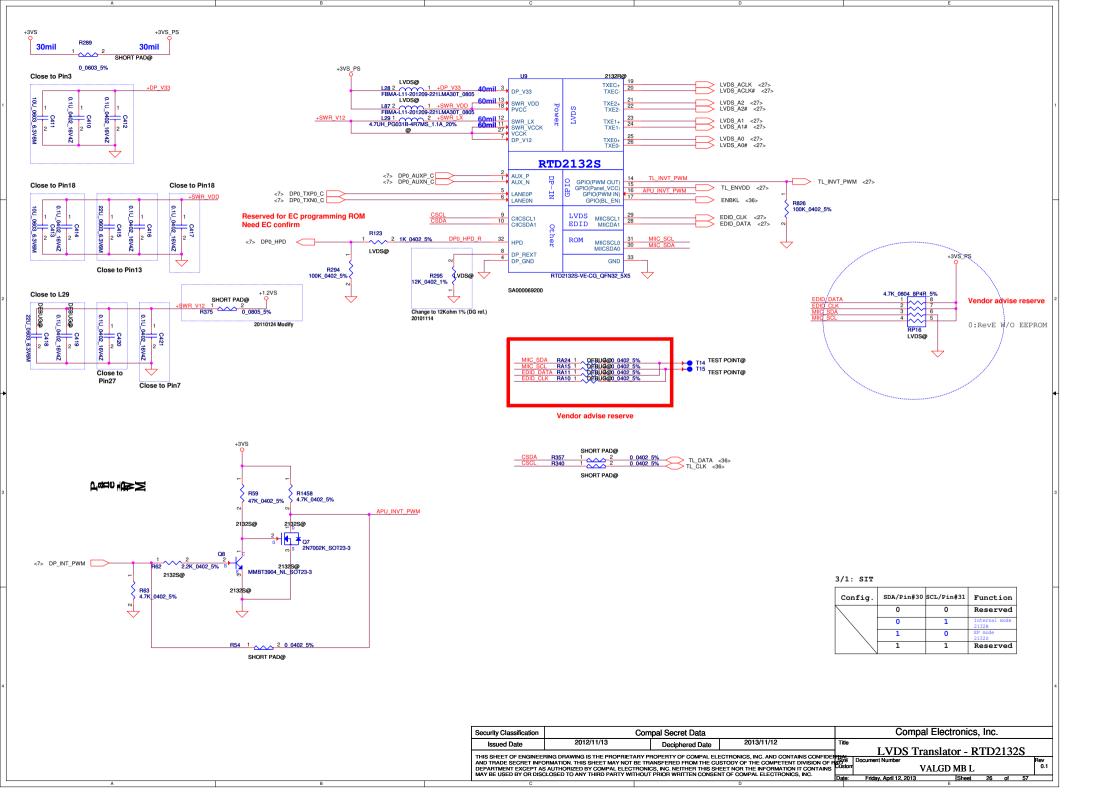


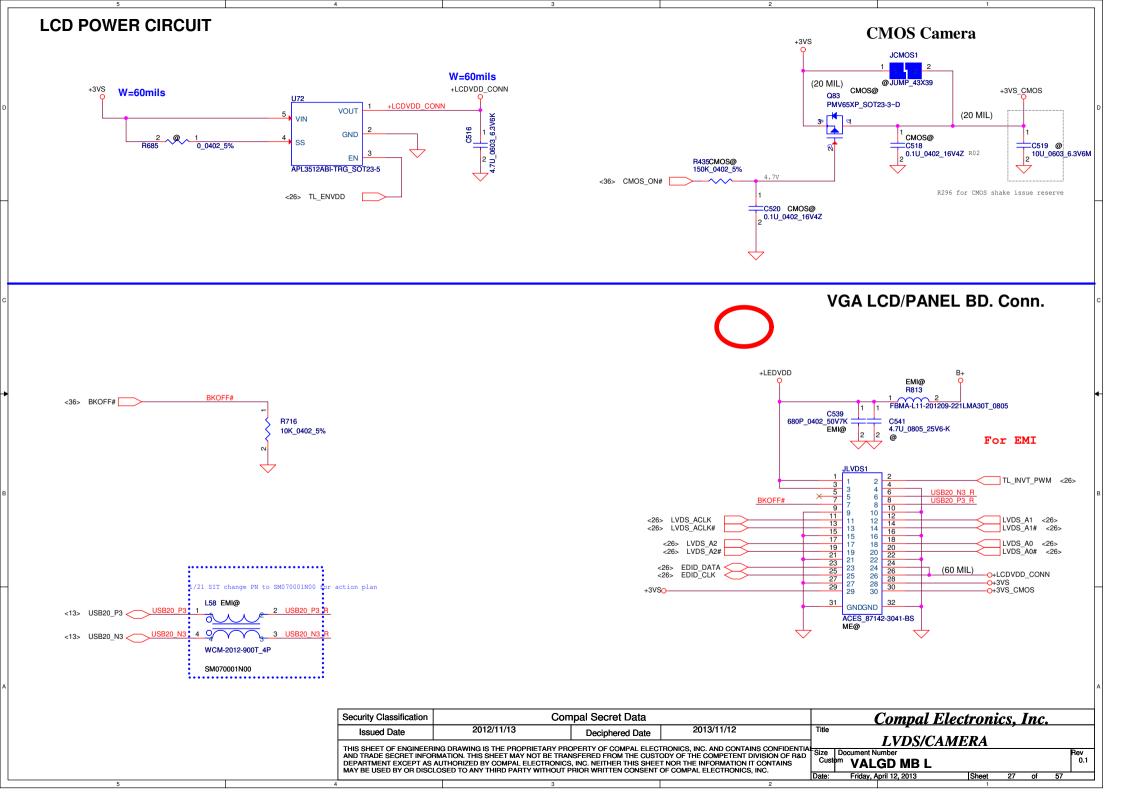


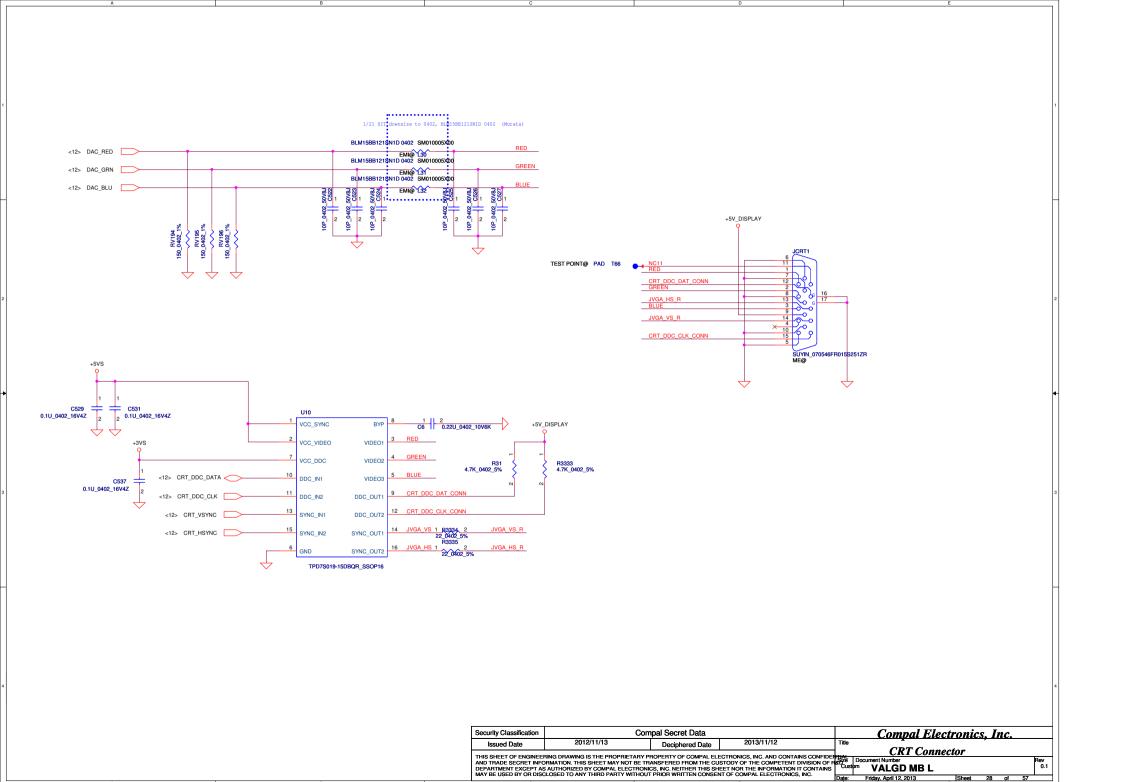


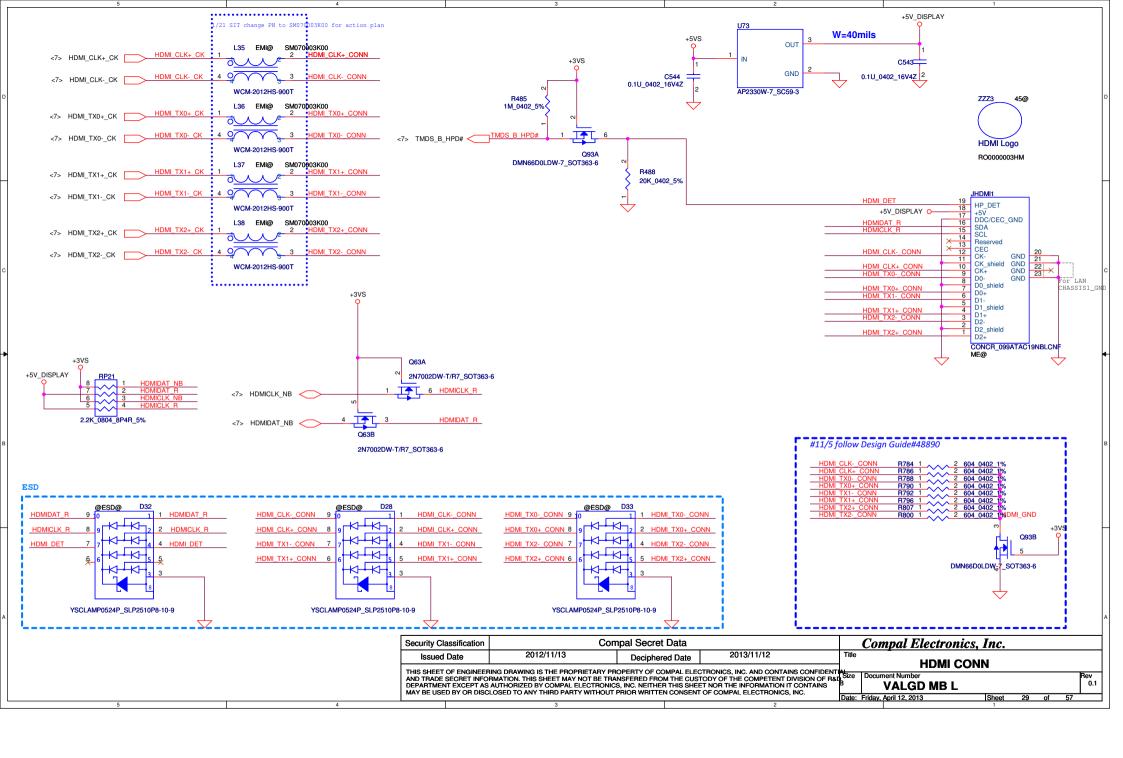


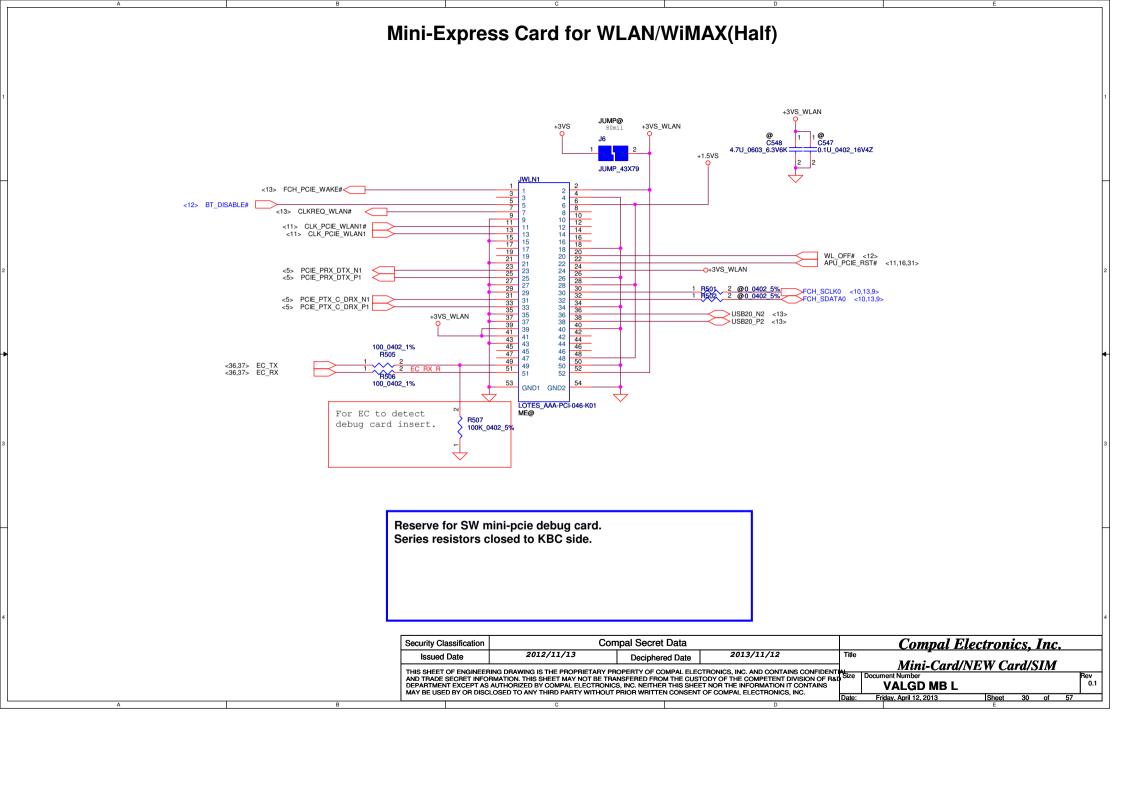


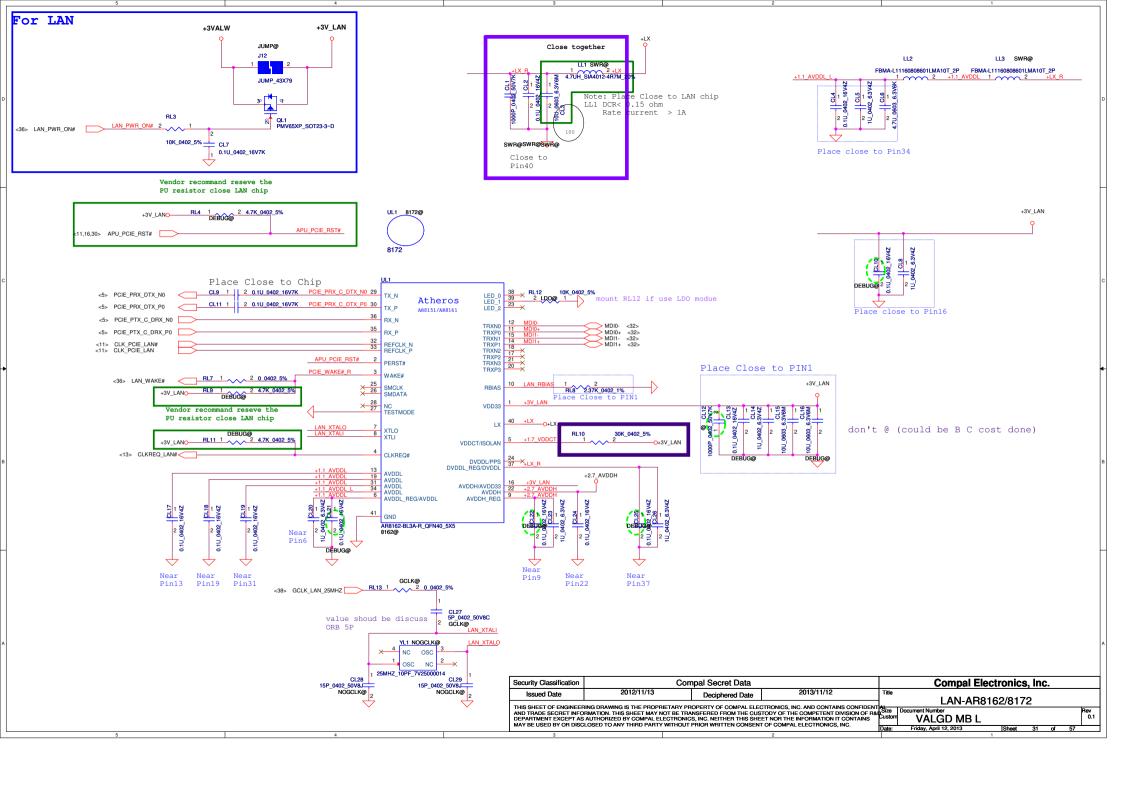


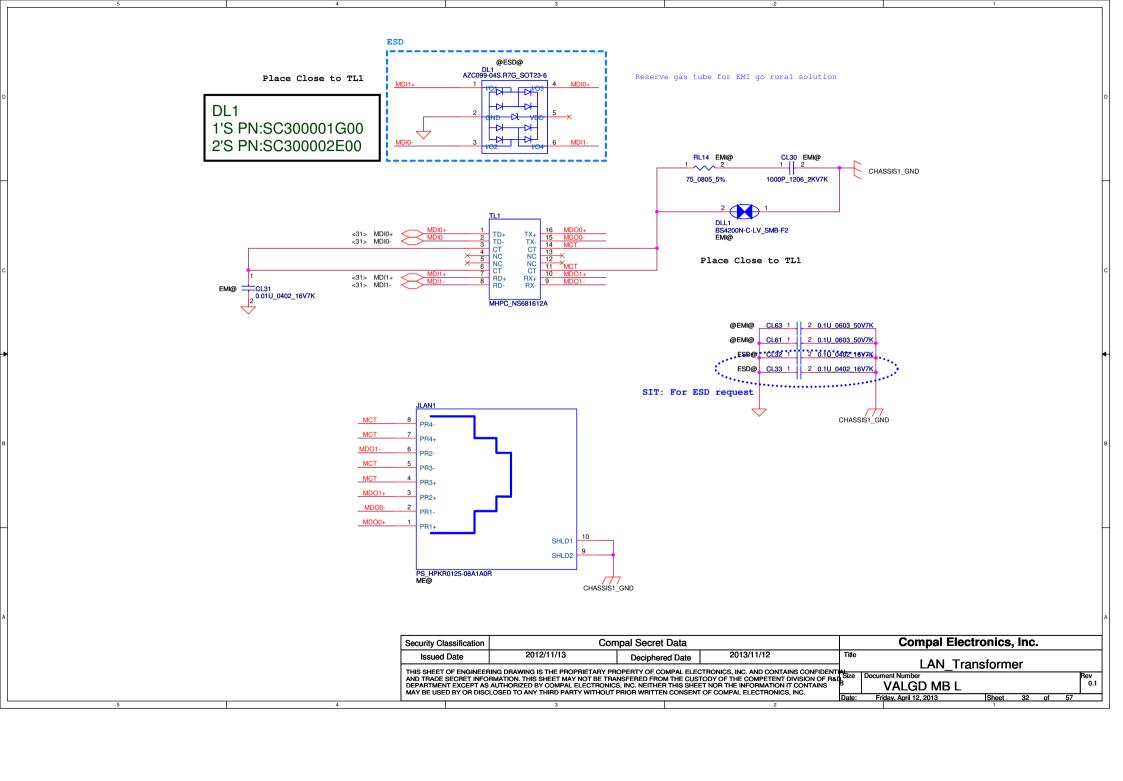


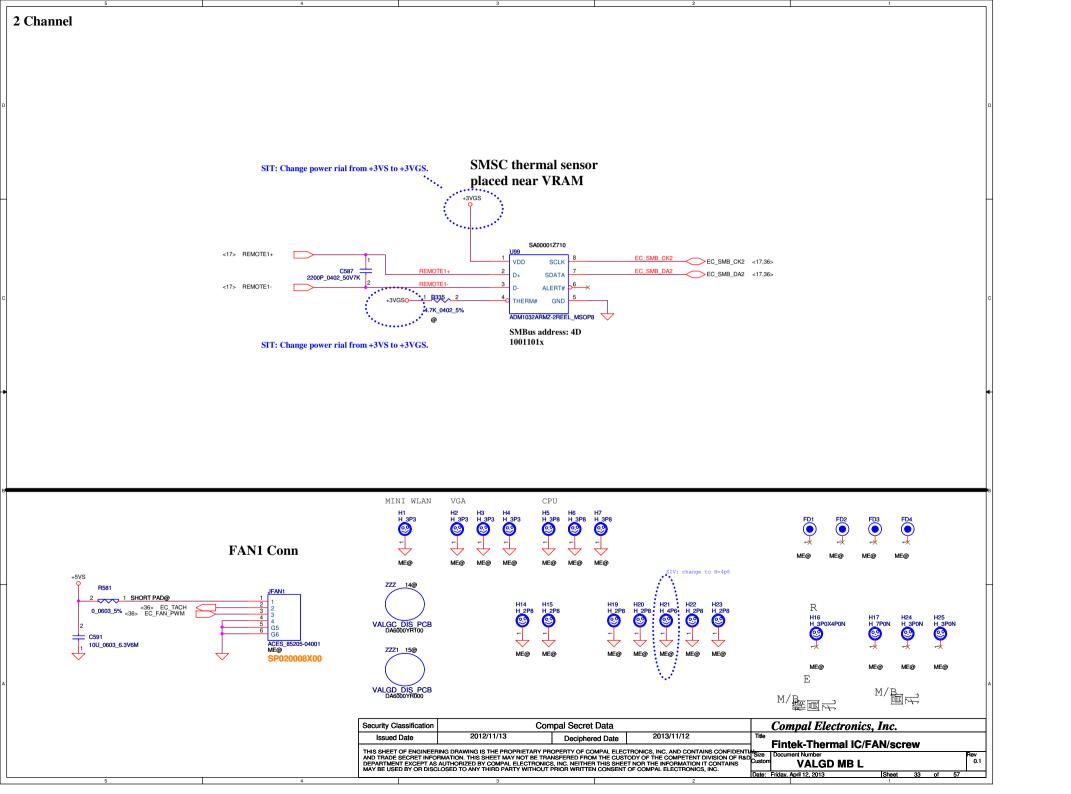


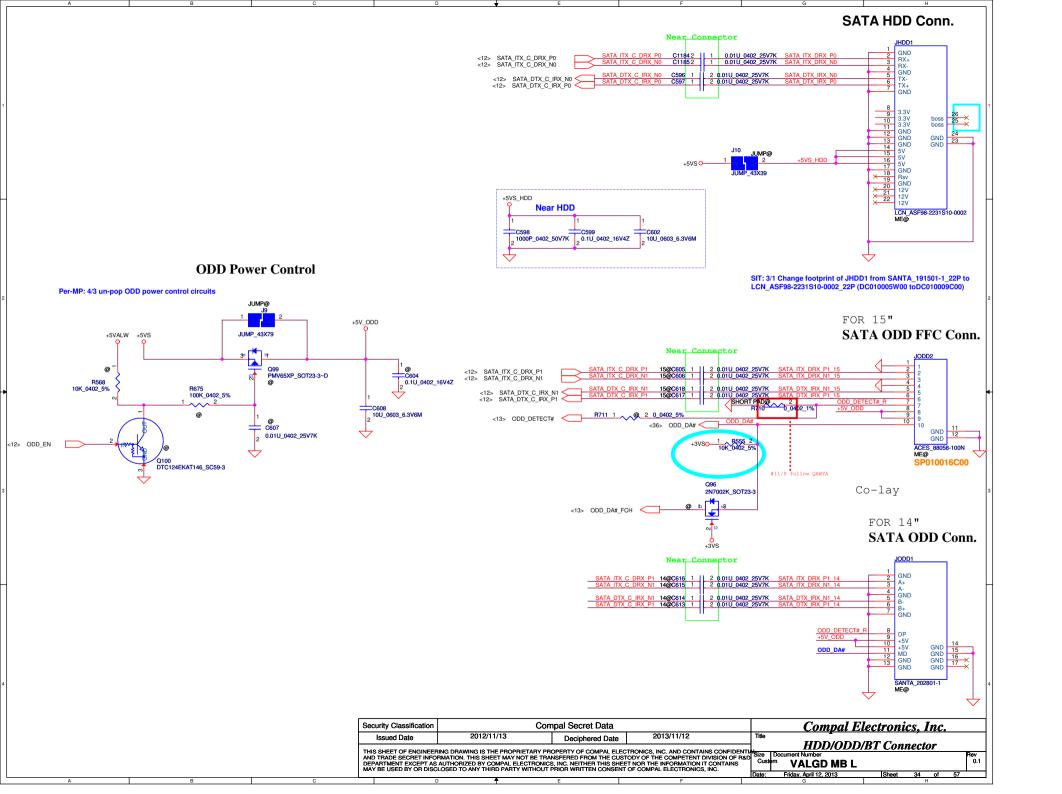


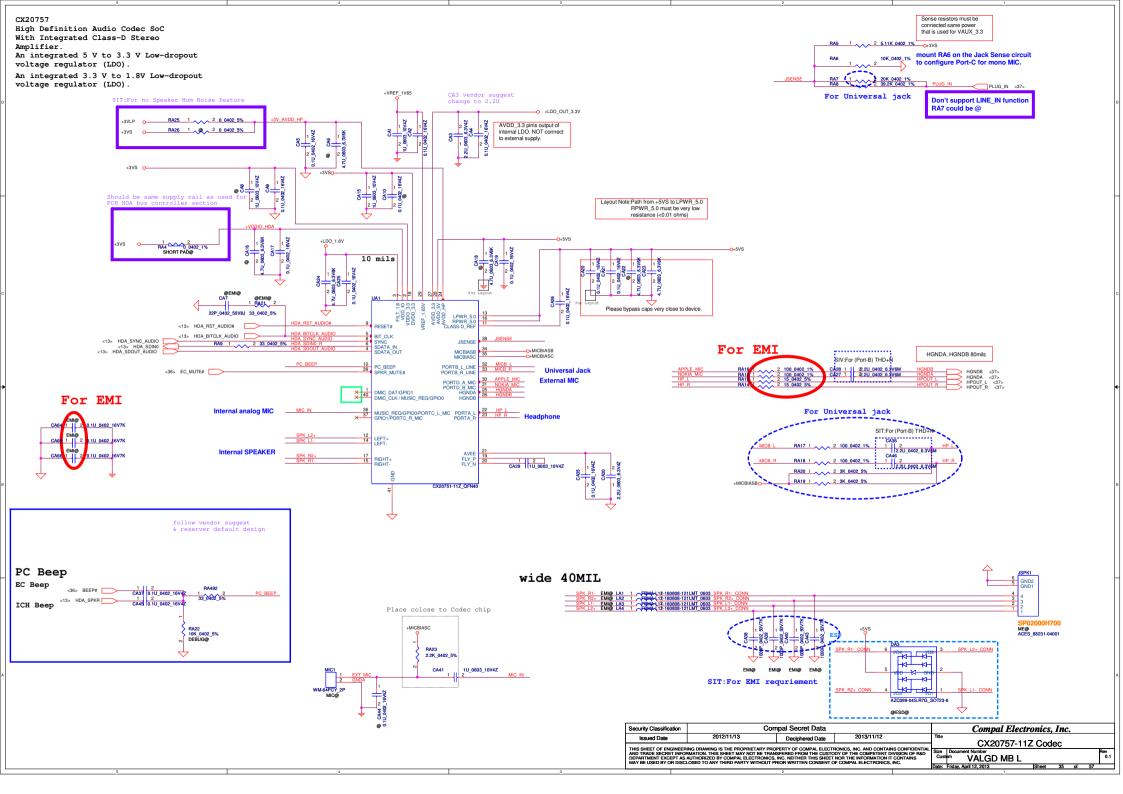


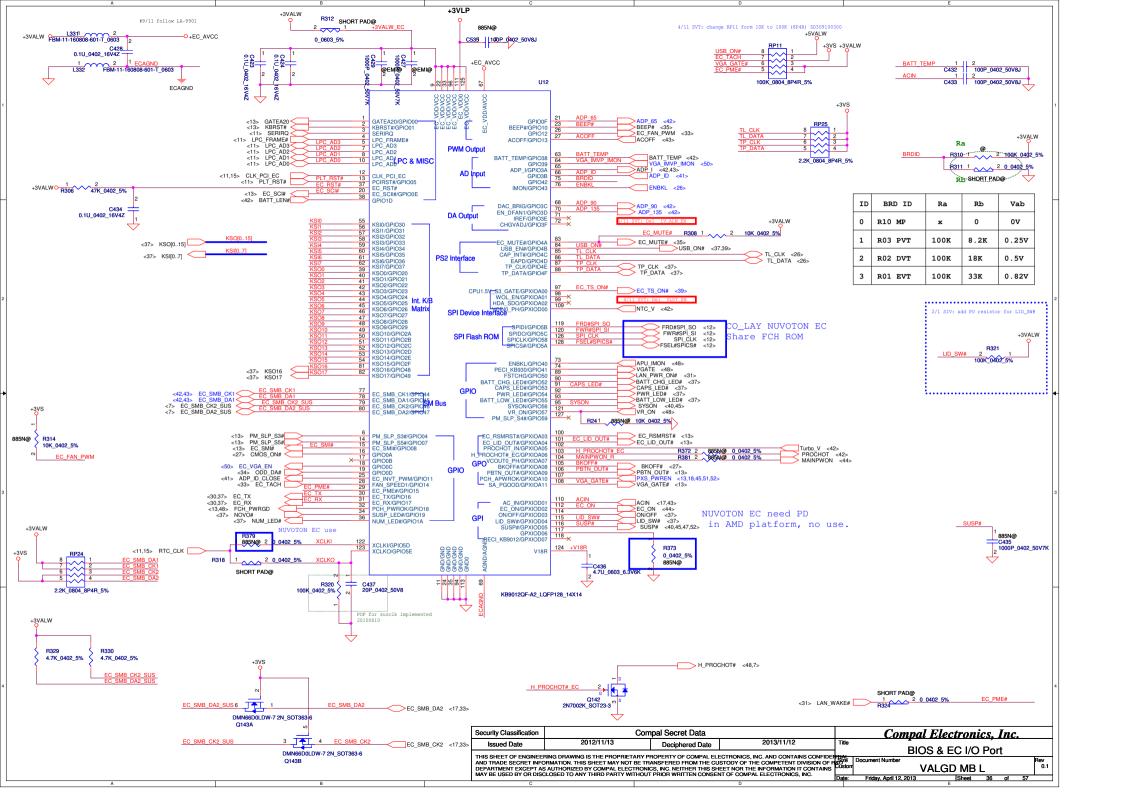


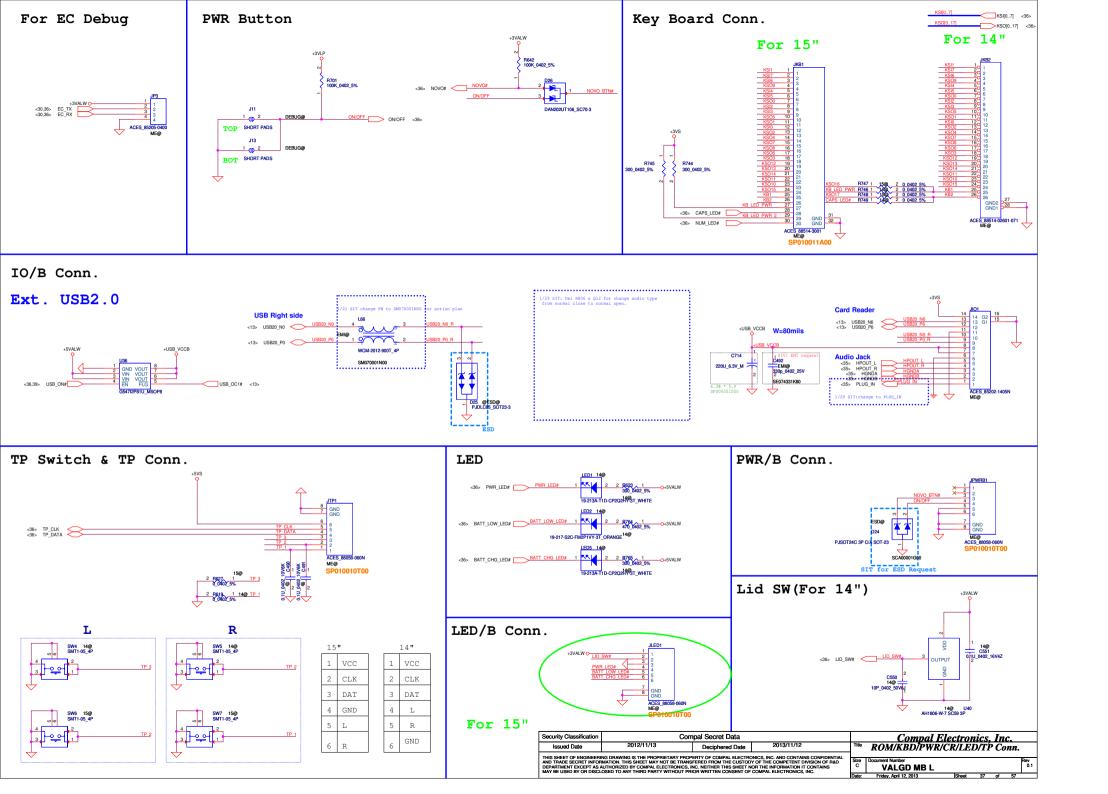


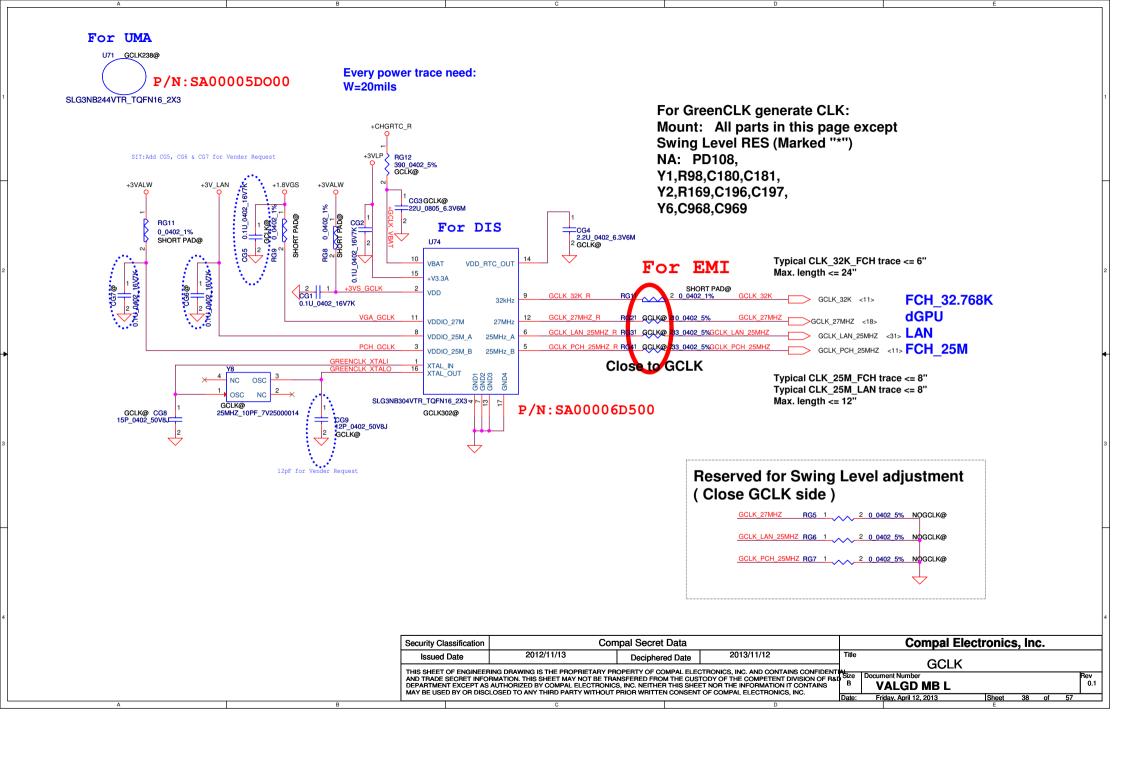






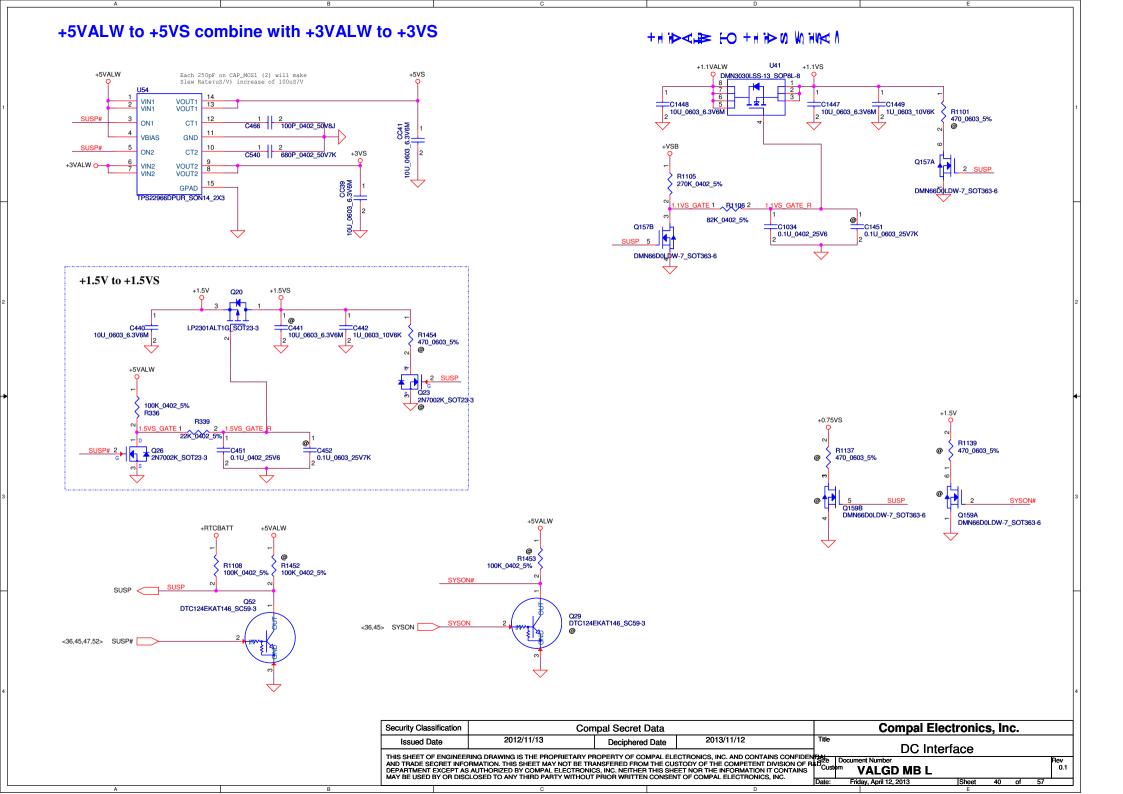


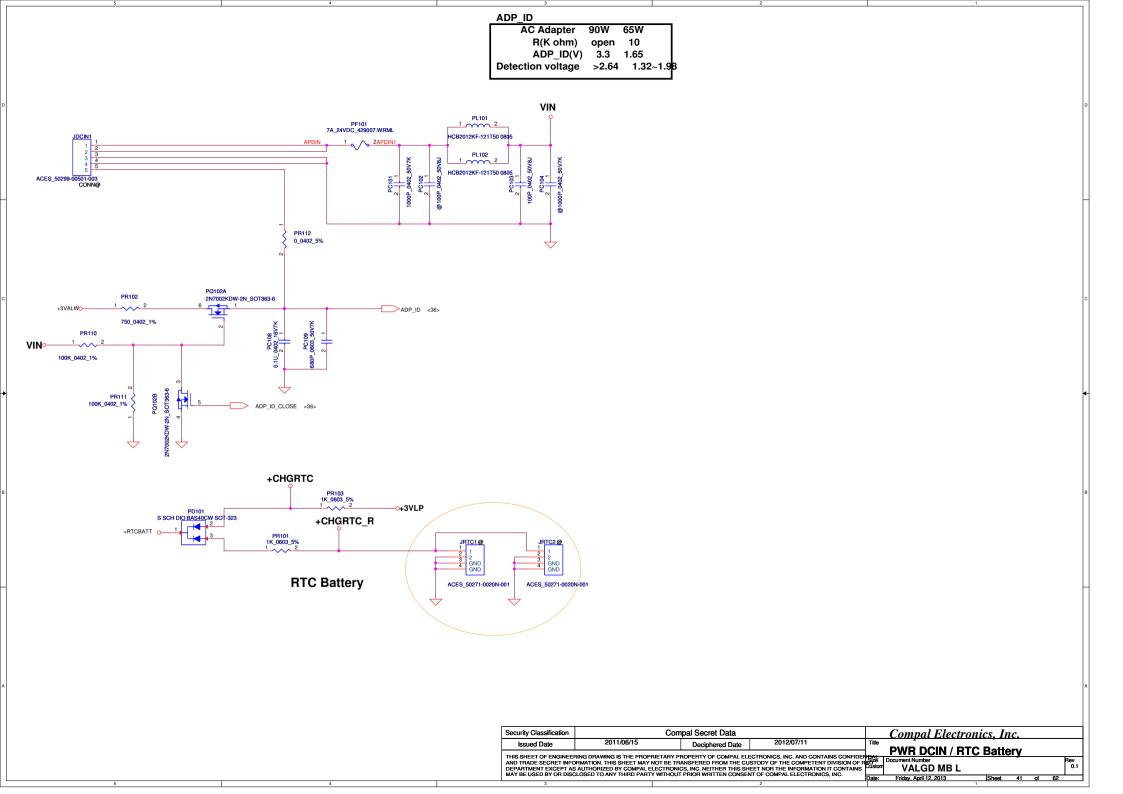


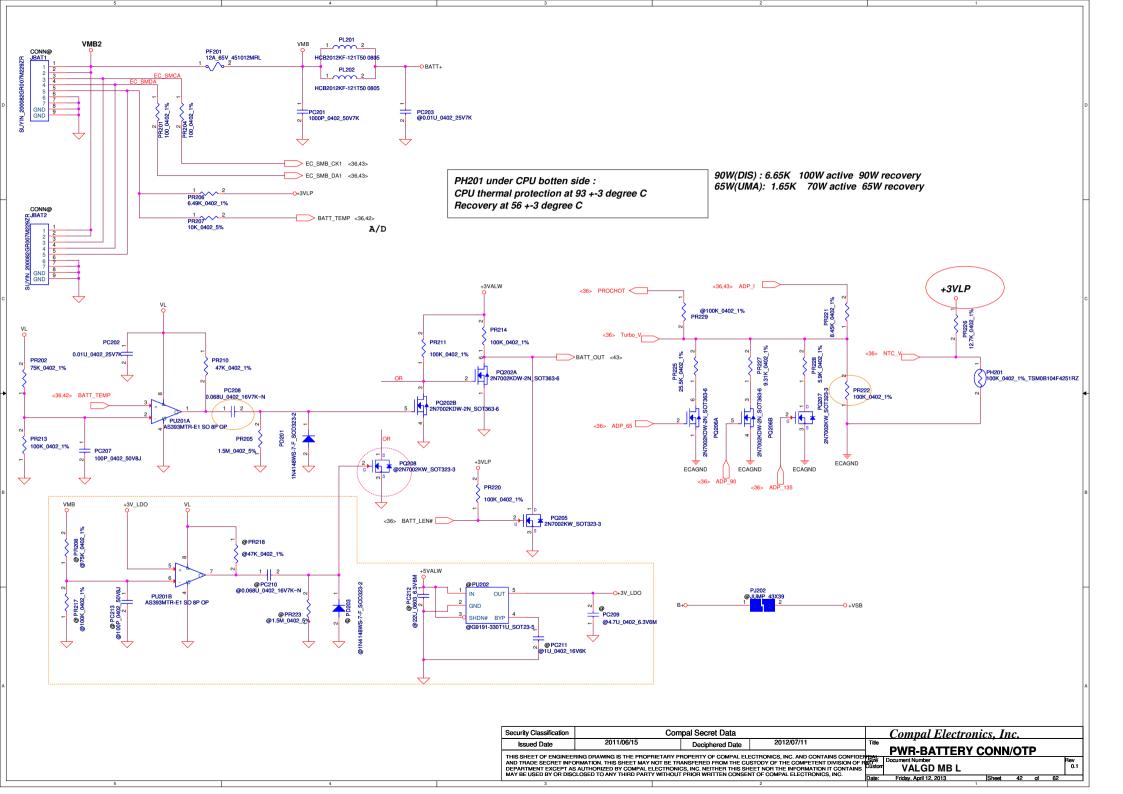


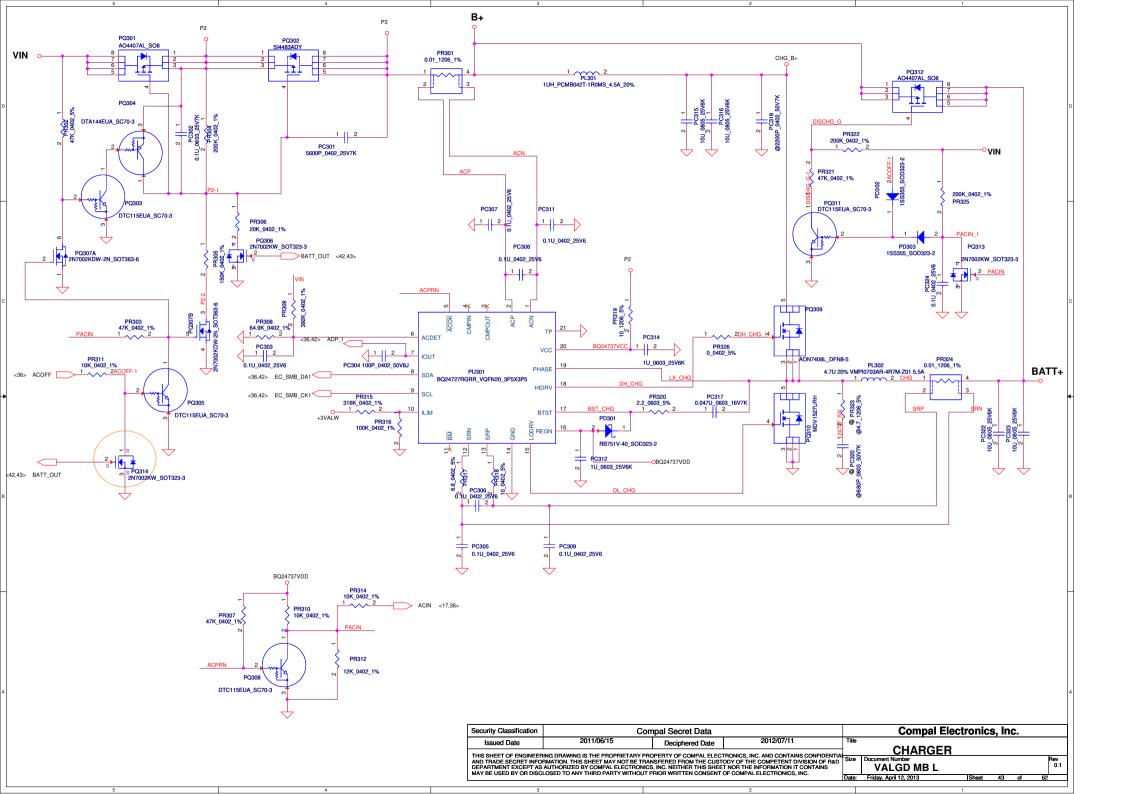
## Touch Screen USB3.0 @ESD@ D30 U3RXDN1 9 0 1 D22 @ESD@ @ESD@ D27 D31 @ESD@ W=80mils 1 | USPACE. H 4 4U3TXDN1 FCH\_USB2.0 FCH\_USB2.0 Left Ext.USB Conn. 1 Left Ext.USB Conn. 2 FCH\_USB3.0 FCH\_USB3.0 WCM-2012-900T\_4P <13> USB3 RX0 N <13> USB3 RX1 N < <13> USB3\_RX0\_P < <13> USB3\_RX1\_P < Place TX AC coupling Cap (C843~C850). Close to connector

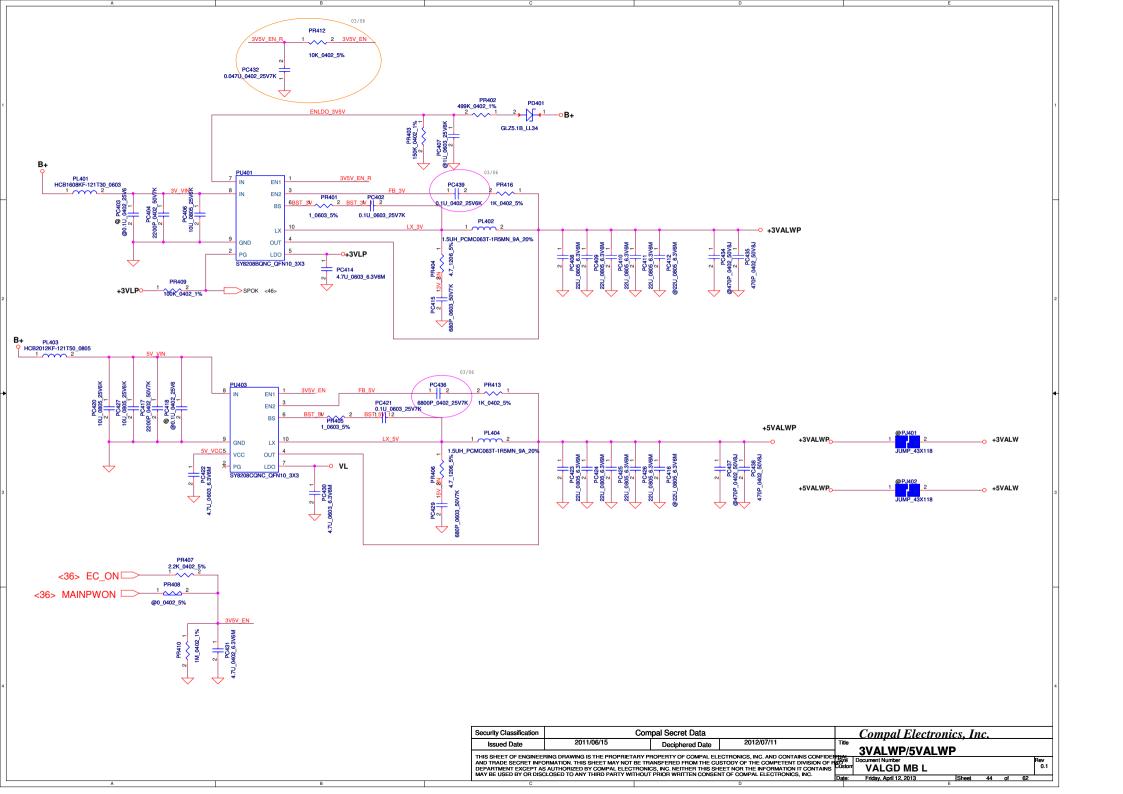
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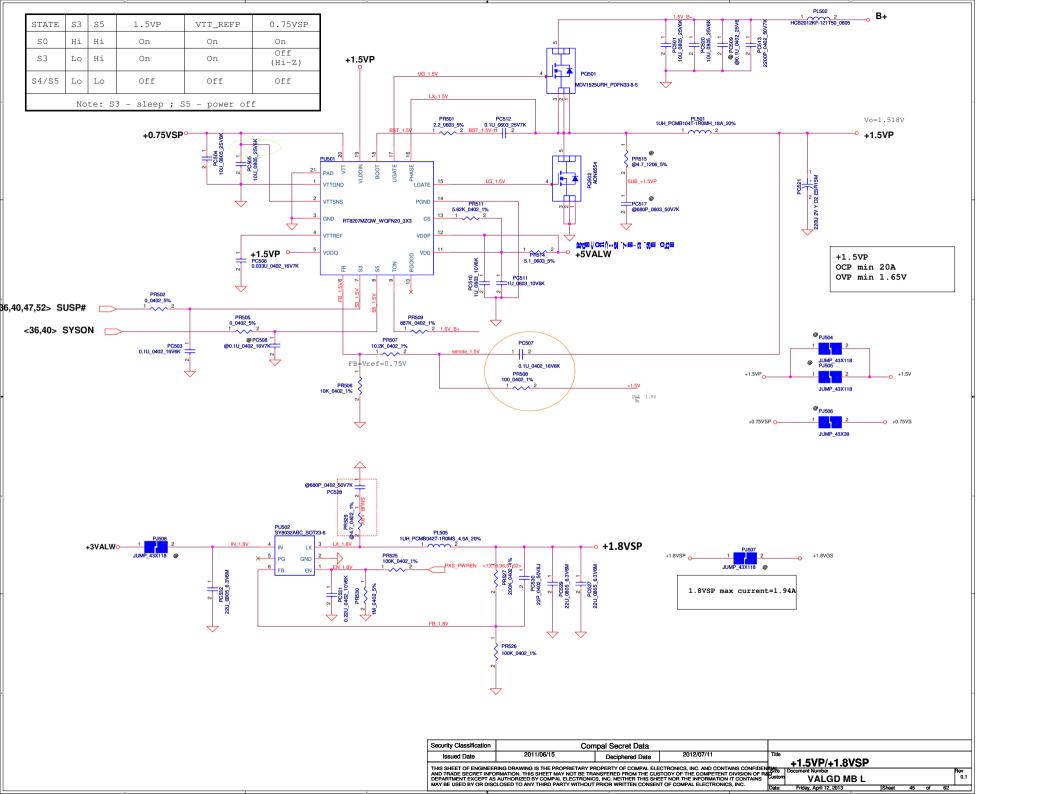


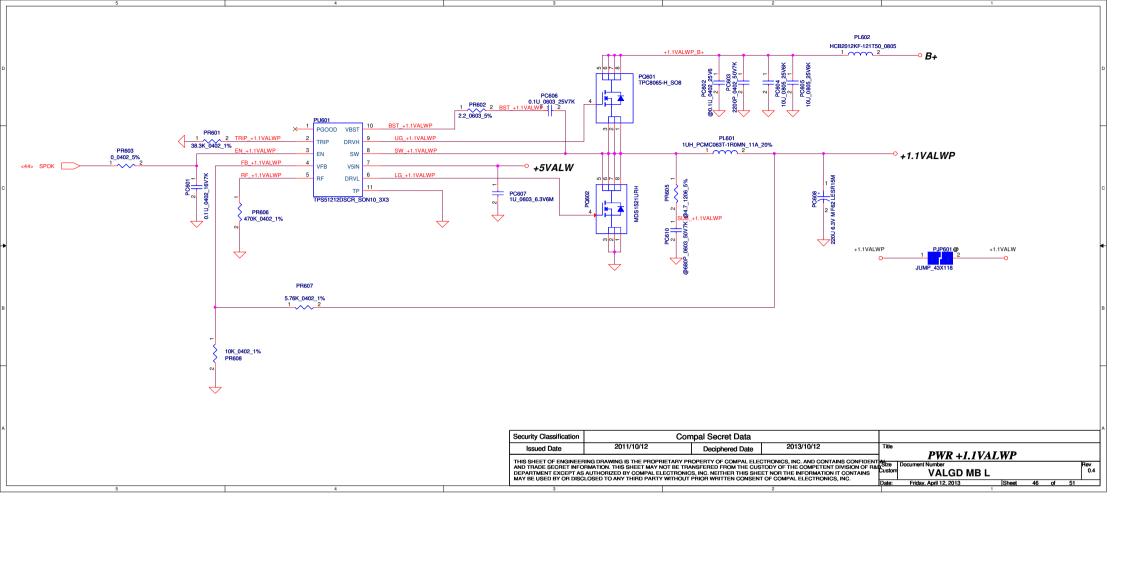


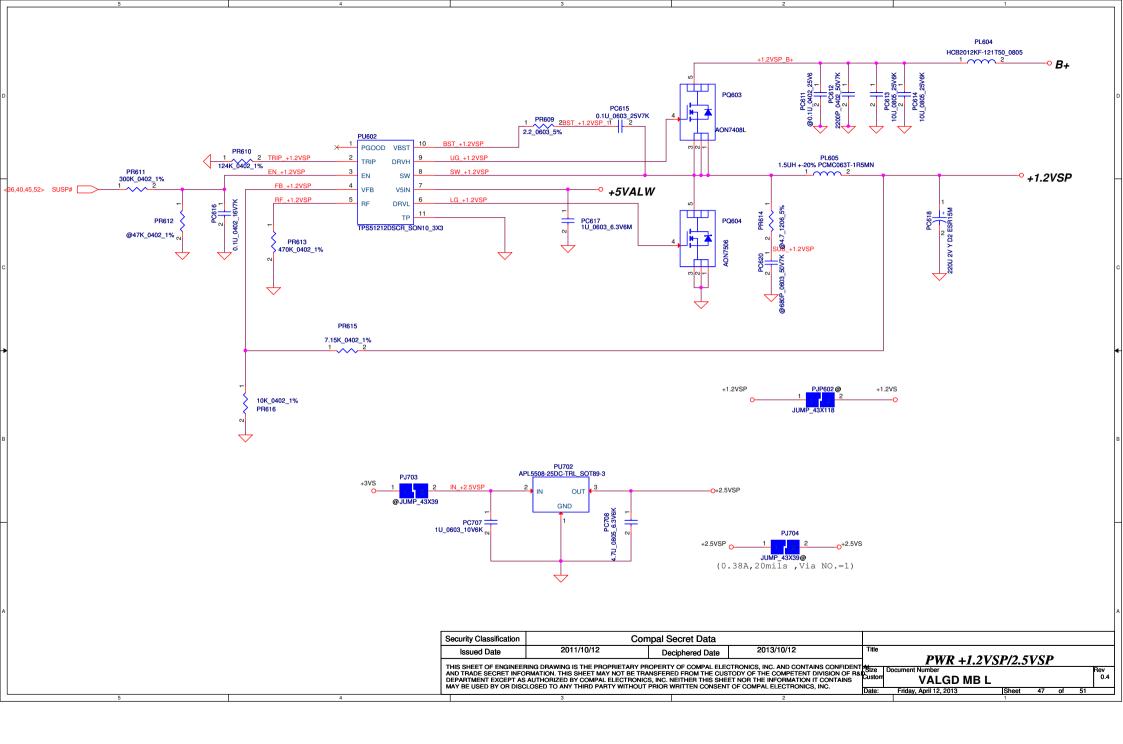


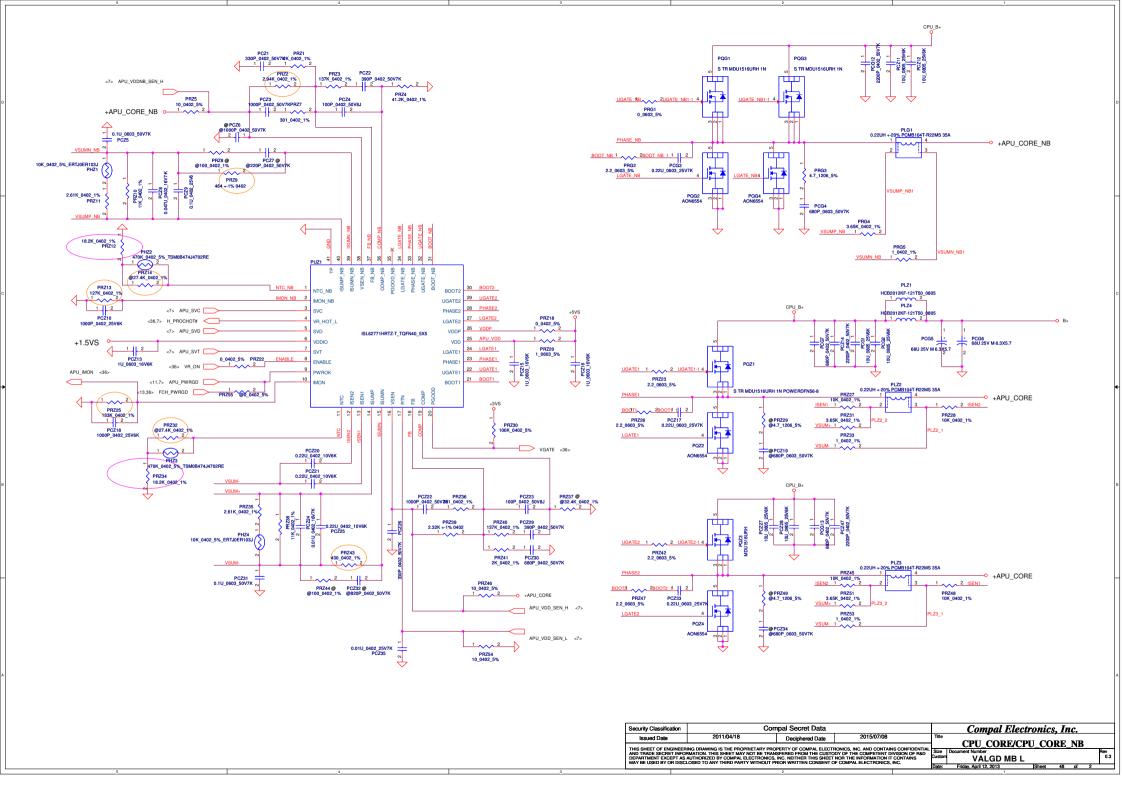


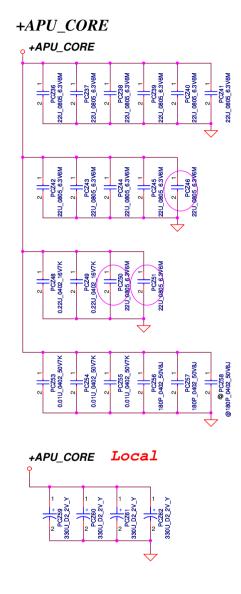




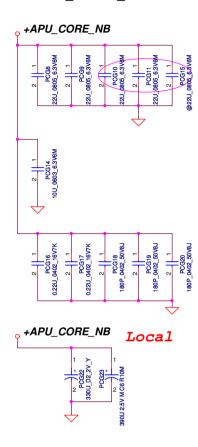






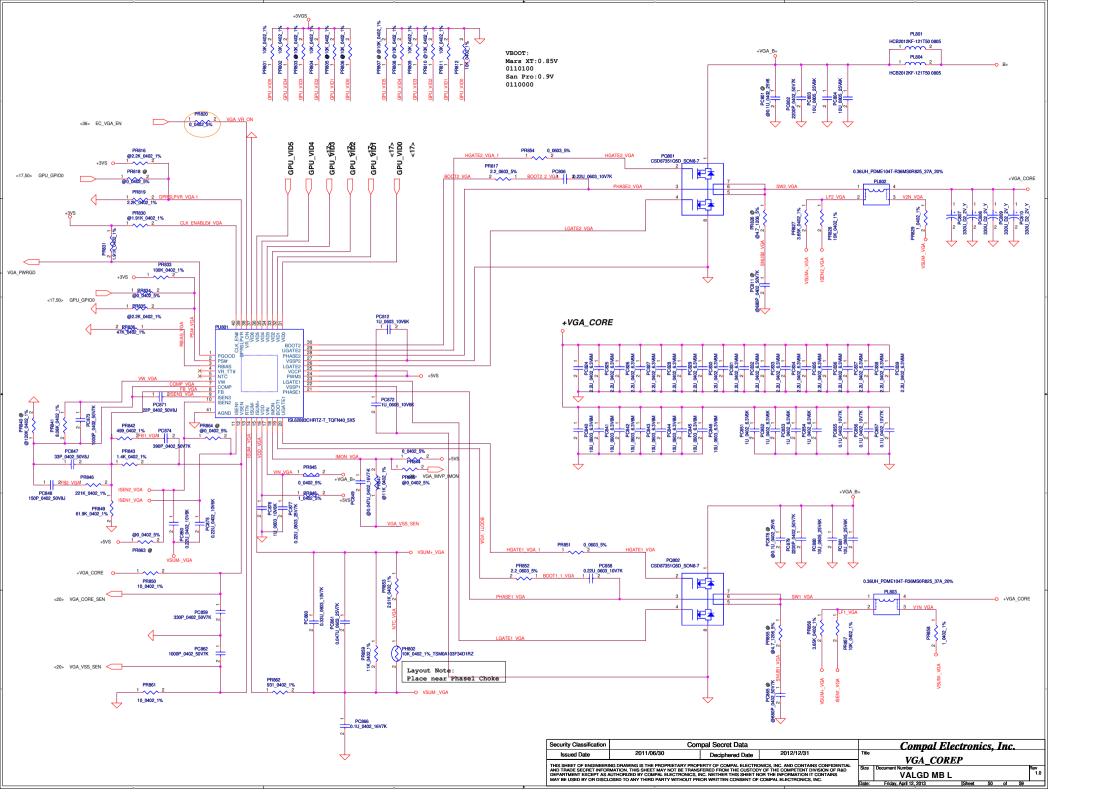


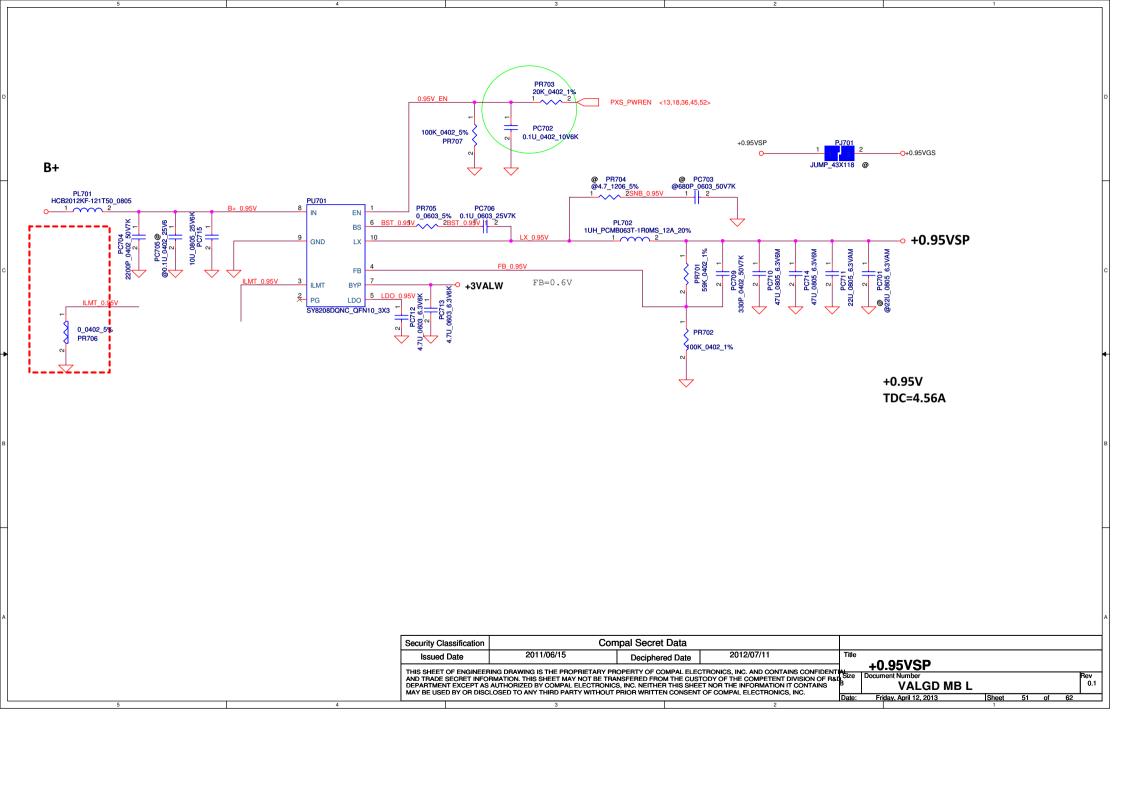
## +APU\_CORE\_NB

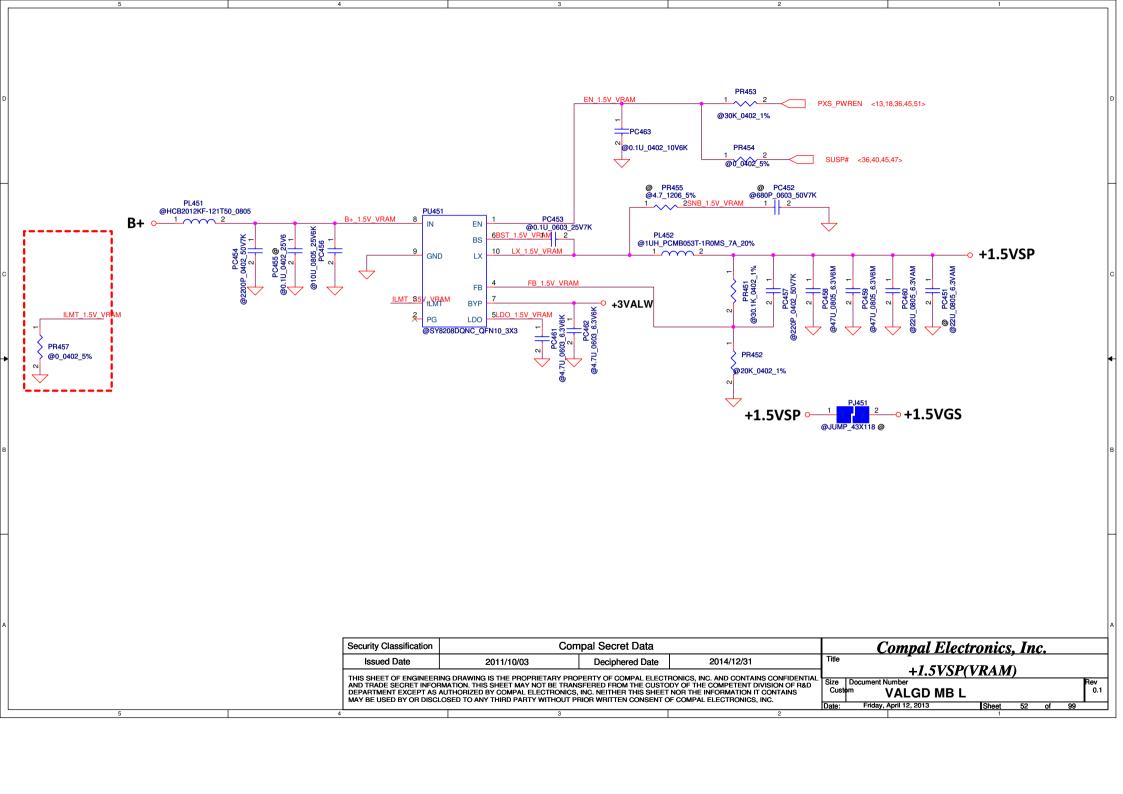


	330uF/9m	22uF/0805	0.22uF/0402	10uF/0603	0.01uF/0402	180pF/0402
APU_CORE	4	10	2		3	2
APU_CORE_NB	2	2	2	1		3

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	Version Change List (P. I. R. List)  Page 1							
Item	Page#	Title	Date	Request Owner	Issue Description			
н	P41	P41-PWR-DCIN / RTC Battery	12/11	PWR	add smart Adapter function	ADD PQ208,PQ102,PR111,PR225,PR228,PR227;Del PR973,PR974,PR972,PR975		
2	P42	P42-PWR-BATTERY CONN/OTP	12/11	PWR	add smart Adapter function	change PQ206,PR110,PR222,PR221,PC109 part number		
3	P51	P51-PWR-+0.95VSP	12/11	PWR	modify 1.5V output level	modify PR7014PR702 to 59Ks100K		
4	P50	P50-PWR-+VGA_CORE	PWR	PWR	EMI rule	Add PC802 CAP		
5	P50	P50-PWR-+VGA_CORE	01/08	PWR	vender FAE requset	change VGA enable pin from SUSP# to EC_VGA_EN		
6	P45	P45-PWR-+1.5VP/+1.8VSP	01/08	PWR	0.75V can't power on	change 0.75V enable pin from SUSP to SUSP#		
7	P42	P42-PWR-BATTERY CONN/OTP	01/08	PWR	modify smart Adapter schematic	modify smart Adapter schematic		
8	P44	P44-PWR-3VALWP/5VALWP	02/23	PWR	Add RC delay for 3V power sequence	Add RC delay for 3V power sequence		
9	P48	P48-PWR-CPU_CORE/CPU_CORE_NB	02/23	PWR	modify over temperature setting	modify over temperature setting		
10	P42	P42-PWR-BATTERY CONN/OTP	02/23	PWR	Units will shut down on Optimized Battery Health mode when plug	out battery modify battery health mode schematic		
11	P45	P45-PWR-+1.5VP/+1.8VSP	02/23	PWR	VRAM transient fail	Add remote sense schematic		
12	P50	P50-PWR-+VGA_CORE	02/23	PWR	AMD change VBOOT SPEC	change Mars XT VBOOT from 1.1V to 0.85V change Sun pro VBOOT from 1.1V to 0.9V		
13	P41,42,48,50	P41,42,48,50	01/10	PWR	Add bead for cost down plan	Add bead for cost down plan		
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	1				on Change List (	P. I. R. Li	ist)	Page 1				
Item	Page#	Title	Date	Request Owner	Issu	e Description			Solution D	Description	Rev.	
1	37		1114		1.SW3 add DEBUG@ 2.add J13	IN3 add DEBUG@ add J13						
2	38		1114		1.change netname form +3VS_VGA to +3VGS 2.change netname form +V1.05S_VCCP to +3VAI 3.remove RG10 4.change U71 P/N form SA000063300 to SA0000		N form SA000057100 to SA0000	5DOOO for UMA				
3	36		1114		1.VR_ON reserve PD 10K							
4	17		1114A		1.remove RV16,RV17							
5	27		1114A		1.reserve RV687,RV92							
6	12,30		1115		1.change netname from PCH_BT_ON# to BT_ON# 2.change netname from PCH_WL_OFF# to WL_OFF	•						
7	40		1115		1.change 1.1VALW to 1.1VS circuit follow Of 2. remove B1138,0158,B1140(include discharg 3.change SVSDN reverse circuit follow QAWYA 4.change SYSON reverse circuit follow QAWYA 5.remove VLDT_EN reverse circuit 6.add +1.5V to +1.5VS follow QAWYA	e of 1.2VS and 2.5VS)						
8	13		1116		1.change netname from LAN_CLKREQ# to CLKREQ	_LAN#						
9	13		1116A		1.change netname from WLAN_CLKREQ# to CLKRE	Q_WLAN#						
10	13,27,30,37		1116B		1.CMOS change port from port1 to port3 2.WLAN change port form port7 to port2 3.USB(R)change port form port8 to port0						•	
11	35		1119C		1.change netname from +3V_PCH to +3VALW							
12	11		1119D		1.remove R84							
13	7		1119D		1.change net name from APU_VDD_RUN_FB_L to? 2.change net name from APU_VDD_SEN to APU_V 3change net name from APU_VDDNB_SEN to APU_VDDNB_SEN	DD_SEN_H						
14	20		1119D		1.change net name from VCCSENSE_VGA to VGA_ 2.change net name from VSSSENSE_VGA to VGA_	CORE_SEN VSS_SEN						
15	36		1119D		1.remove EC_VGA_EN 2.remove VGA_AC_DET							
16	34		1120A		1.reserve Q96,R711							
17	7		1120C		1.remove C159,C161,C210,C164 2.change net name from LVDS_A1 to DPO_TXP1 3.change net name from LVDS_A1# to DPO_TXN1	c _c						
18	26		1120C		1.add RP26,R241,R242							
19	26		1121C		1.remove R301,R302,R826,C422,U11							
20	27		1121C		1.remove R687							
21	19		1122		1.remove CV54,CV55,CV56,CV57,CV58,CV59							
22	20		1122		1.remove CV96,CV97							
23	36		1122A		1.remove C431,R305,C438,C439							
24	7,26,36		1123A		1.remove C113,C115,RP26,R239-242 for eDP ci 2.add R826 3.add "EMRKL"signal 4. change EC GPIO(VGATE and EC_TS_ON)	rcuit						
25	17,33,39		1126A		2. Remove Q11 3. Set RV24,RV25,QV3 are 0	1. Change C736 from SGA00003000 to SE00000T780 2. Remove Q11 3. Set RV24,RV25,QV3 are 0 4. Add REDV11 to UV1.AF29 & REMOTE1- to UV1.AG29						
26	38		1127		1. Change net name from +3VGS to +1.8VGS or	1. Change net name from +3VGS to +1.8VGS on U71 pin11						
27	27		1127A		1.Change net name from DISPOFF# to BKOFF# 2.Update PO4 table							
28	33		1127A		1add ZZZ for MB PCB							
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Version Change List (P. I. R. List) Request Issue Description Solution Description Title Page# Date Rev. **Owner** 1.remove R801,R207,RV40,RL13,CL27 for GCLK circuit 1128 29 11,18,31,38 2.GCLK circuit in p.38 1.remove GCLK@ in RL3,CL7,QL1 2.change LL1 P/N to SHI00008W00 1128 1.change U40 P/N to SA00005LN00 28 1128A 1.change RP22 to RV94~RV96 1128B 1.change CL30 P/N to SE067102K80 11 1128B 1.change CLK\_PCIE\_LAN/CLK\_PCIE\_LAN# form port0 to port3 2.change CLK\_PCIE\_WLAN1/CLK\_PCIE\_WLAN1# from port1 to port2 28 1128B 1.add R3334,R3335 1129 1 add Dain Dail Dais Daid Didso Didso 26 36.41 1129 1.add signal "ADP ID CLOSE" for smart adapter function 1130 32.33 1.remove OPT@ of C587 2.change from @EMI@ to EMI@ for CL30 1130 1. change can form .22u to .1u for PCTE Gen2 5.16 35 1130 1.change shot pad to .1u for CA64~CA66 39 1204 1.change JTS1 conn to SP010013W10 12,30 1204A 1.remove BT\_ON#,add BT\_DISABLE# 43 1204A 1.RP9.4 connect to +1.5V\_APU,R348.1 connect to +1.5VS for leakage issue 1.add R801,R207,RV40,RL13,CL27 for GCLK circuit 2.add GCLK circuit in p.38 11.18.31.38 1204B 1.change net name form NOVO# to EC\_FAN\_PWM in EC 2.change net name form EC\_FAN\_PWM to NOVO# in EC 3.change net name form ENBKL to APU\_IMON in EC 4.change net name form APU\_IMON to ENBKL in EC 1.change RG2 to 10ohm,RG3 to 33ohm,RG4 to 33ohm 2.U74.2 change from +3V\_LAN to +3VALW 3.8 1206 1206A 1.change C736 to SE00000PL00(0805 package) 4.8 3.8 1210 1.add GCLK@ in RG2.RG3.RG4 55,56 1210A 1.add P55.P56 1.update BOM Structure Table 2.change U3 symbol to SA00003K820 3.change U35,U36 symbol to SA00003TV00 4.change U99 P/N to SA00001Z710 5.0 1212 03.12.33.37.39 1.update PWR circuit for BOM 1220 1.change LV7 BOM structure from PX@ to SHORT PAD@ 53 40 1220 1.remove @ in Q157A 54 20 1224 1 add TEST DOINTS to TUIS 55 18 1224 1.change net name from PXS PWREN to PXS PWREN# in OV2.2 56 28 1224 1 remove C528 based on LA-9901 DVT schematic 1224 1.change JKB1 from SP01000WK00 to SP010011A00 2.change JTP1, JPWRB1 from SP010014M10 to SP010010T00 1224 34 1.change JODD2 from SP01001FJ00 to SP010016C00 Security Classification Compal Secret Data Compal Electronics, Inc. 2008/09/15 2012/12/31 Issued Date

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			1	Versi	on Change List (	P. I. R. Lis	t)	Page 3			
Item	Page#	Title	Date	Request Owner		Description			Solution	Description	Rev.
59	35		1224		1.change JSPK1 from SP02000RR00 to SP02000H	00					
60	37		1224		1.change JLED1 from SP01001A900 to SP010010T0	0					
61	33		1225		1.change U99 from SA00001Z710 to SA000067P00						
62	24,25		1225		1.change CHB form PX@ to MARS@						
63	26		1225		1.change Panel PWM circuit 2132R@						
63	29		1225		1.change Q93 & Q95 to Q93A & Q93B						
64	27		0105		1.Change BID R311=>18K						
65	35		0107		1.RA12,RA16 change to 100-ohm., RA13, RA14 to	15-ohm, ADD CA27,CA28 to 1uF	7				
65	36		0108		1.add PXS_PWREN & EC_VGA_EN						
66	14 ,34		0108		1.Change R177 ,180 & R550 from 0805 short page	to Jumper (J14, J15, & J10)					
66	35		0110		1.RA22=>DEBUG@ for Beep 2. CA28 CA27=>2.2u i	or THD+N					
67	27, 32 and 37		0110		1.R813=>220 ohm Bead 2.Add C492 for EMI requ	est 3.DLL1=>EMI@					
68	33		0111		1.ADD 22Z & 2ZZ1 for 14"_DIS & 15"_DIS pcb						
69	12		0114		1.ADD GPI054 for RTD2132R@ 2.change U99						
70	33		0116		1.change H21 from 2P8 to 4P6 2.change U99 to	1001101x (4D)					
71	39		0116		1.add C737 &C735@ for USB droop (follow Intel	)					
72			0121		1.change D24 to SCA00001G00 for ESD request						
73	28		0121		1.L30, L31 & L32 downsize to 0402,SM010005X00						
74	39		0121		1/21 L51,L55,L58 &L66 change PN to SM070001N0	0 for action plan					
75	29		0121		1/21 L35,L36,L37 &L38(HDMI) L49,L50,L53 & L54	(USB3) change PN from SM07000	01800 to SM070003K00 for act	ion plan			
76	10		0126		SIT: change C145 from OS-Con to POLY						
77	37		0129		1/29 SIT: Del R806 & Q12 for change audio typ	e from normal close to normal	open.				
78	36		0201		2/1 SIV: add PU resistor for LID_SW#						
79	35		0221		1.upgrade capacitors of CA36 & CA46 from 1uF	to 2.2uF/X5R 2.AVDD_HP conn	nect to standby power rail (	+3VLP) for prevent speaker hum nois	e issue.		
80	20		0221		1.Change Cap of CV66 to 220U 4V Y D2 ESR15M =	SGA00000Y80 for PWR request					
81	38		0221		1.add CG5 on 1.8VGS for GCLK 2.reserve CG6 a	CG7 for vender request.					
82	22~25		0221		1. p22 & p23==>Channel B Mars@ 2.p24 & p25=	=>ChannelA PX@					
83	35		0225		1. add speaker bypass Cap CA38,CA39,CA40 & CA	43 for EMI requirement					
84	07		0226		1. add C438 100pF on H_THERMTRIP# for ESD rec	uirement					
85	34		0301		SIT: 3/1 Change footprint of JHDD1 from SANTA	_191501-1_22P to LCN_ASF98-2	2231\$10-0002_22P (DC010005W0	0 toDC010009C00)			
86	34		0301		Del CV168 ,CV159,CV160 &CV189 for VRAM body s	ize issue					
87	37		0301		change C492, SE00000FD80 to SE074331K80 by Sc	urcer requirement.					
88			0301		LV4,LV10,L3,L6,L9,L11& L77 Downsize to 0402	BLM15AX221SN1D (Murata) ,SM01	1000MK00 by Sourcer requirem	rnt.			
89	36		0301		Add R311=8.2K for SIT						
90	11		0301		Change R85 from 0 ohm short pad @ to 33 ohm E	MI@					
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1			Version	on Change List (P. I. R. Lis	t) Page 3		
Item	Page#	Title	Date Request Owner	Issue Description		Solution Description	Rev.
91	26		0301	1.add R1461 for RTD2132R ,MIIC_SDA :MIIC_SCL=0 : 1			
92	35		0301	1.Change +VDDIO_HDA power rail from +3VALW to +3VS.			
93	26		0304	1.add R1462 for RTD2132R ,MIIC_SDA :MIIC_SCL=0 : 1 2.Del RP16.3 & RP16.4			
94	12,13		0304	1.Change R367 from 10K to 100K. 2.Change R234 from 10K to 100K			
94	32		0305	1.add CL32 & CL33 for ESD request.			
95	32		0306	1.add R236 & R237 (LVDS_SEL) for C build only.			
96	8		0306	1.add J3 for 1.5V			
96	33		0306	1.Change Power rail of the U99 from +3VS to +3VGS.			
97	12		0306	1.Change Power rail of the GPIO54 from +3VALW to +3VS.			
98	12		0307	1.Change +1.5GVS enable pin from +VSB to +5Valw for Eup lot 6.			
99	12,36		0311	1.Change BOM structure of R367 & R368 to 0,2132S only 2.R237 & R236 =>0			
Pre-MP 100	33		0311	1.Change U99 to SA00001Z710			
Pre-MP 101	12,36 & 26		0403	1.Reduce part count for RTD2132R only			
Pre-MP 102	12,36 & 26		0403	1.Reduce part count for RTD2132R only			
Pre-MP 103	34		0403	1.ODD Power Control cuicuits =>@			
Pre-MP 104	33		0410	1.Change H17 form H_8PON to H_7PON SD309100280			
Pre-MP 105	36		0410	1.Change RP11 form SD309100280(10K) to SD309100300(100K)			
Pre-MP 106	18		0410	1.Change RV41 to 47K for Erp Lot6			
Pre-MP 107	18		0410	1.Change RV37 from 20Kto 100K ,RV38 from 20K to 0 ohm.			
Pre-MP 108	18		0410	1.Change RV37 from 20Kto 100K ,RV38 from 20K to 0 ohm.			
Pre-MP 109	36		0411	1.Del Net VLDT_EN & 1V_ALW_EN			
Pre-MP 110	7, 13		0412	1.change C438 from 100p to 1000p. 2. add C439, 1000p for ESD request.			
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